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Takahashi

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(54) **ORGANIC EL DISPLAY PANEL
PRODUCTION METHOD**

(56) **References Cited**

U.S. PATENT DOCUMENTS

4,219,822 A * 8/1980 Paranjpe B41J 2/07
347/40
5,443,922 A 8/1995 Nishizaki et al.
(Continued)

FOREIGN PATENT DOCUMENTS

CN 1435318 A 8/2003
CN 102742357 A 10/2012
(Continued)

OTHER PUBLICATIONS

Jp 2006159703 Google Patents.*

(Continued)

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U.S.C. 154(b) by 0 days.

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(30) **Foreign Application Priority Data**

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B05D 1/26 (2006.01)

(Continued)

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(2013.01); **B05D 1/36** (2013.01); **B05D**
3/0254 (2013.01); **H01L 51/56** (2013.01);
H05B 33/10 (2013.01)

(58) **Field of Classification Search**

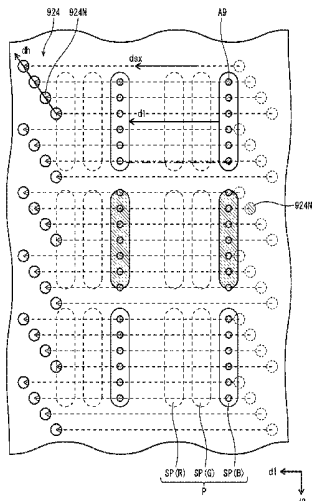
CPC ... H01L 51/00; B05D 1/00; B05D 3/00; B41J
2/00; B41J 25/00; H05B 33/00

See application file for complete search history.

(57) **ABSTRACT**

A method for manufacturing an organic EL display panel, including: forming first electrodes over a substrate; defining, above the substrate, pixel formation regions lining up in a row direction and a column direction, by forming banks over the substrate; applying ink to each pixel formation region by causing a plurality of nozzles lining up in a straight line to discharge the ink to the pixel formation regions while displacing the nozzles relative to the substrate in a scanning direction; drying the ink to form functional layers in the pixel formation regions; and forming a second electrode at a position covering the pixel formation regions. In the application of ink, an angle θ between the scanning direction and the row direction is set to more than 0° and less than 90° and each nozzle applies the ink across a plurality of rows of the pixel formation regions.

6 Claims, 15 Drawing Sheets



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H01L 51/56 (2006.01)

JP H05-163488 A 6/1993
 JP 2000-202357 A 7/2000
 JP 2004-111074 A 4/2004
 JP 2005-296854 A 10/2005
 JP 2006-159703 A 6/2006
 JP 2006159703 * 6/2006
 JP 2010-005619 A 1/2010
 JP 2010-266636 A 11/2010
 WO 2012/017491 A1 2/2012

(56)

References Cited

U.S. PATENT DOCUMENTS

2003/0137557 A1 * 7/2003 Nakamura B41J 2/14
 347/44
 2003/0184613 A1 10/2003 Nakamura et al.
 2005/0052120 A1 3/2005 Gupta et al.
 2006/0227163 A1 * 10/2006 Kwon B41J 2/16538
 347/33
 2012/0032207 A1 2/2012 Nishiyama et al.
 2013/0126844 A1 5/2013 Nishiyama

FOREIGN PATENT DOCUMENTS

GB 2 336 553 A 10/1999

OTHER PUBLICATIONS

Chinese Search Report issued in corresponding Chinese Patent Application No. 201580018620.0, dated Jun. 2, 2017; with partial English translation.
 International Search Report and Written Opinion issued in International Patent Application No. PCT/JP2015/001781, dated Jun. 16, 2015; with English translation.

* cited by examiner

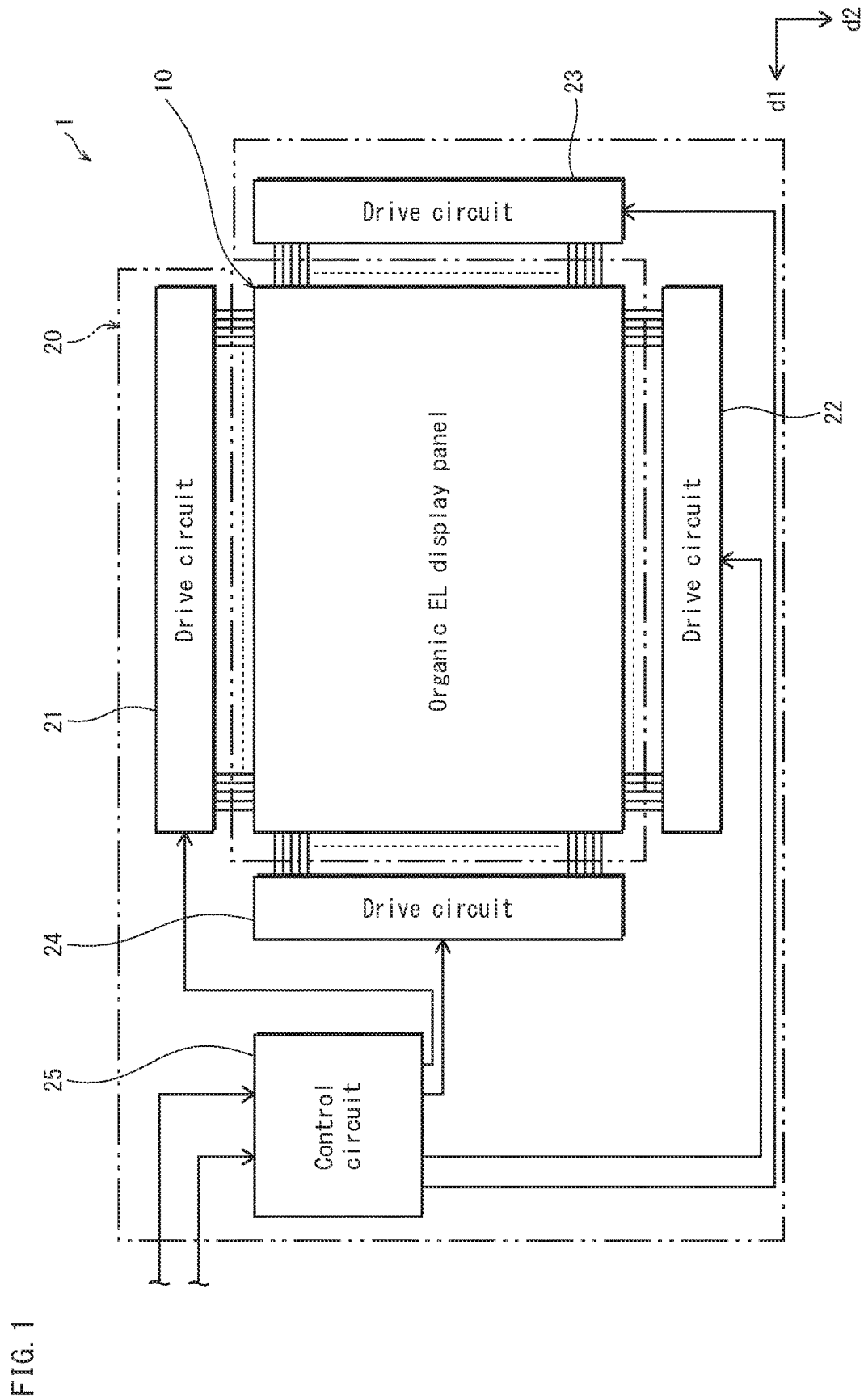


FIG. 2

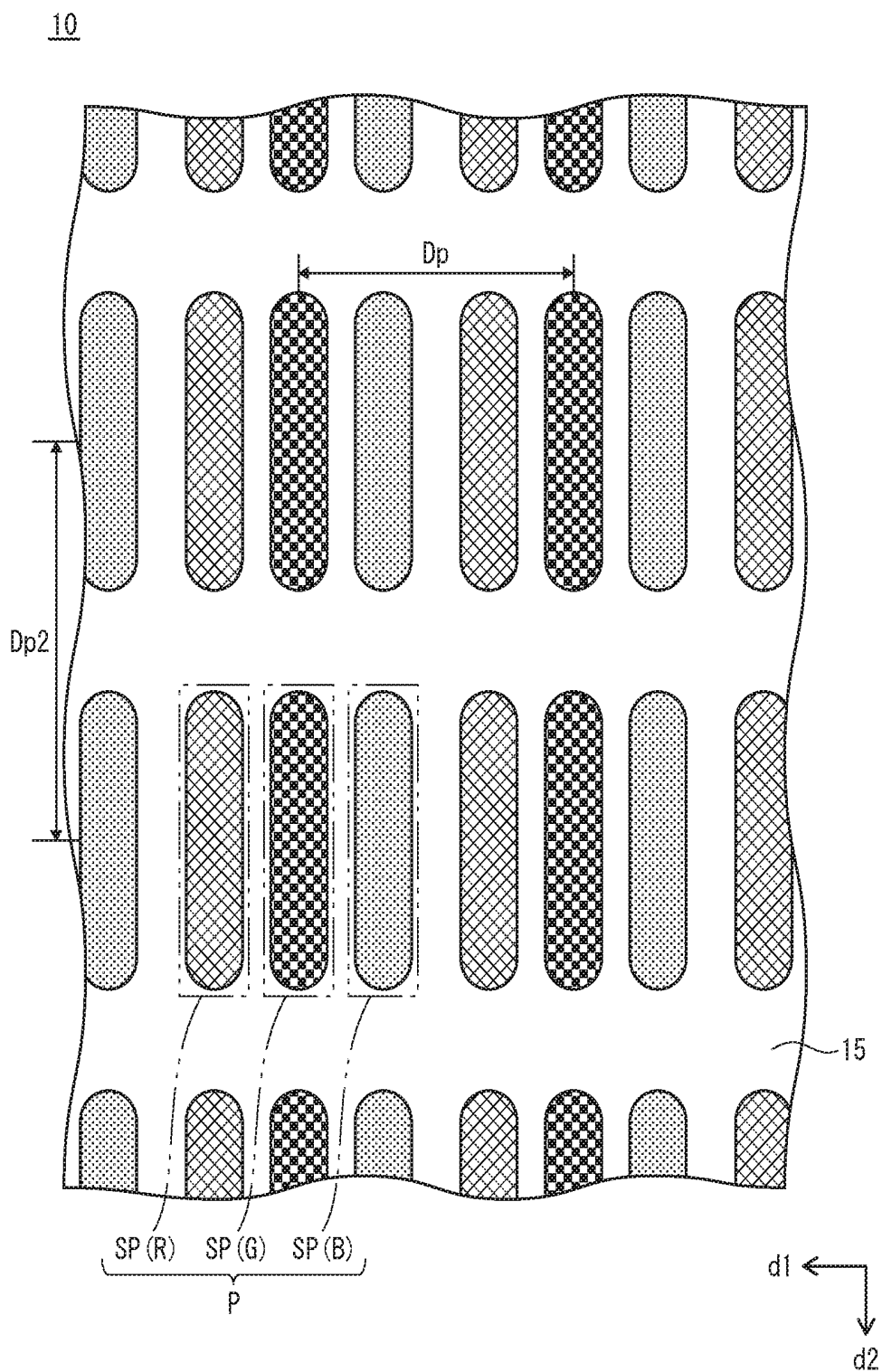


FIG. 3

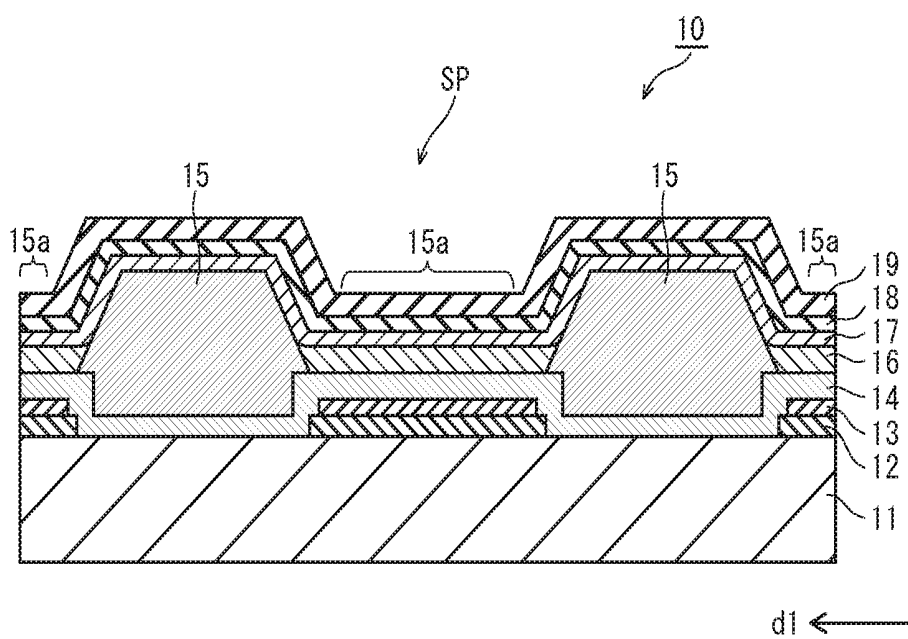


FIG. 4

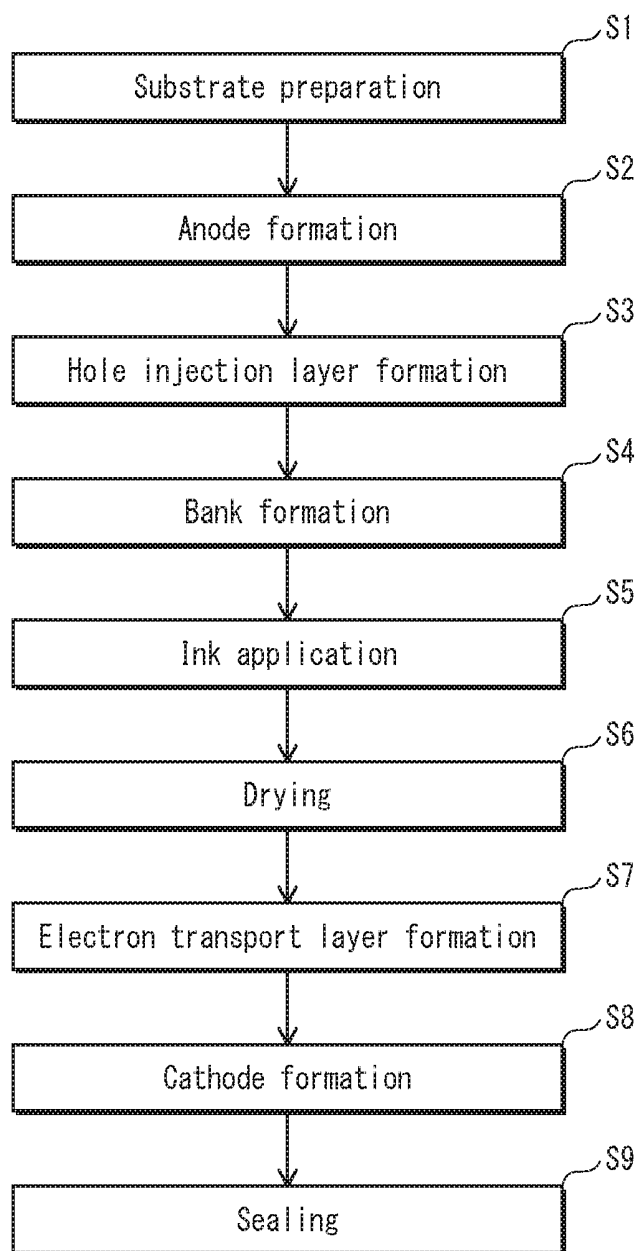


FIG. 5A

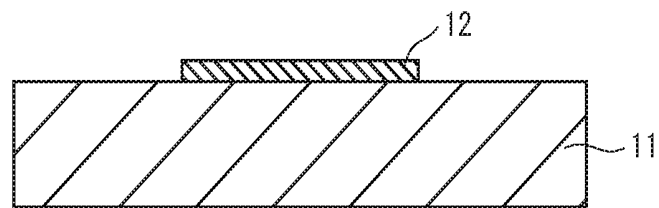


FIG. 5B

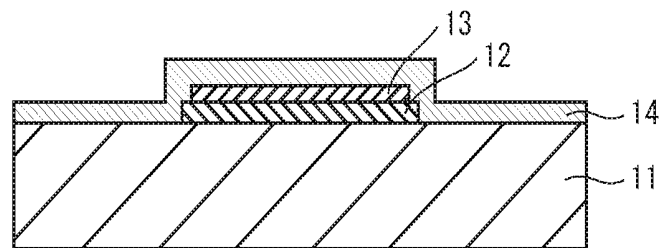


FIG. 5C

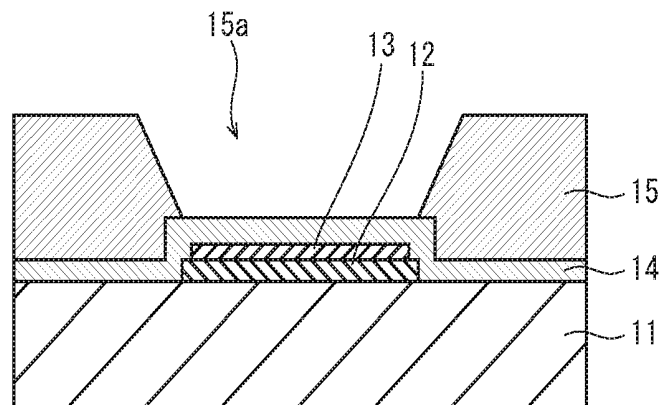


FIG. 6A

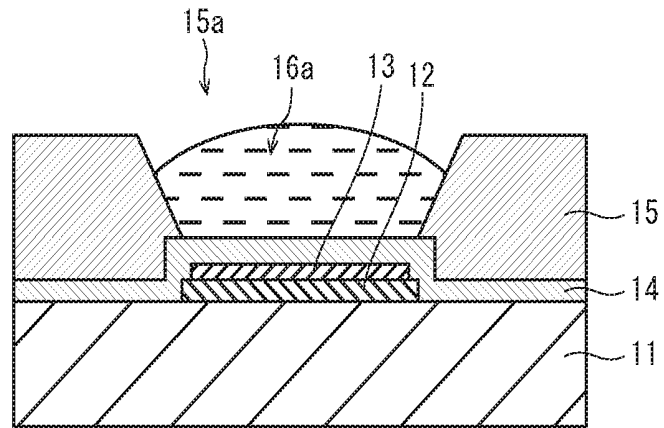


FIG. 6B

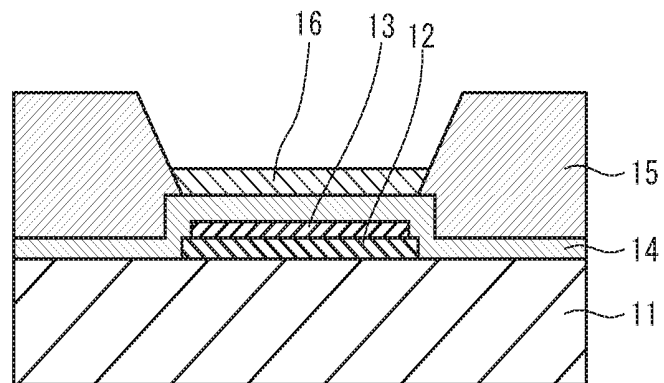


FIG. 6C

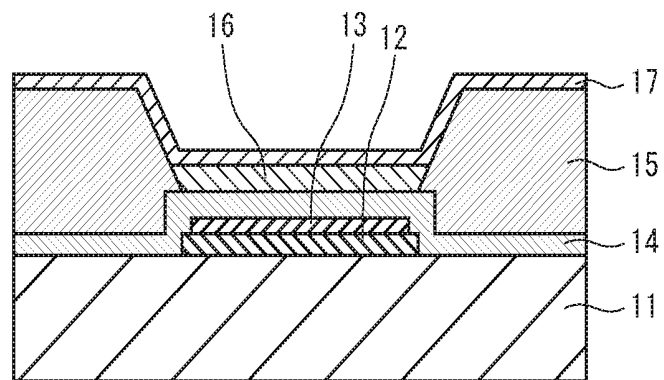


FIG. 7A

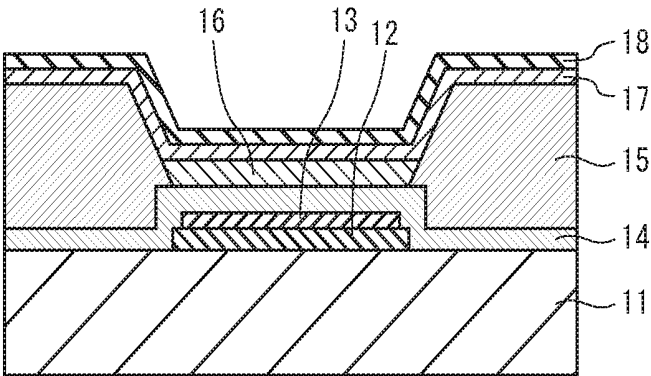
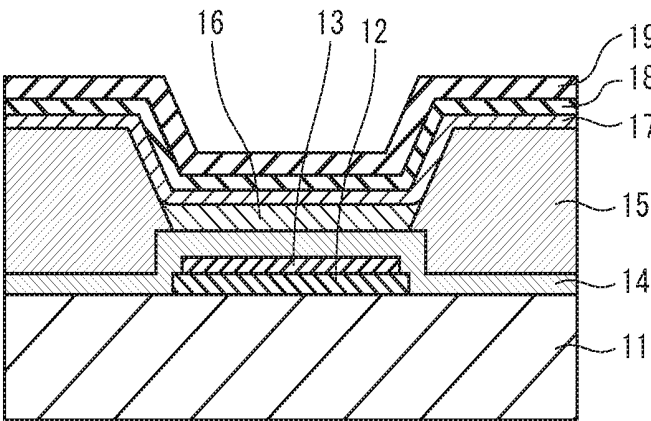


FIG. 7B



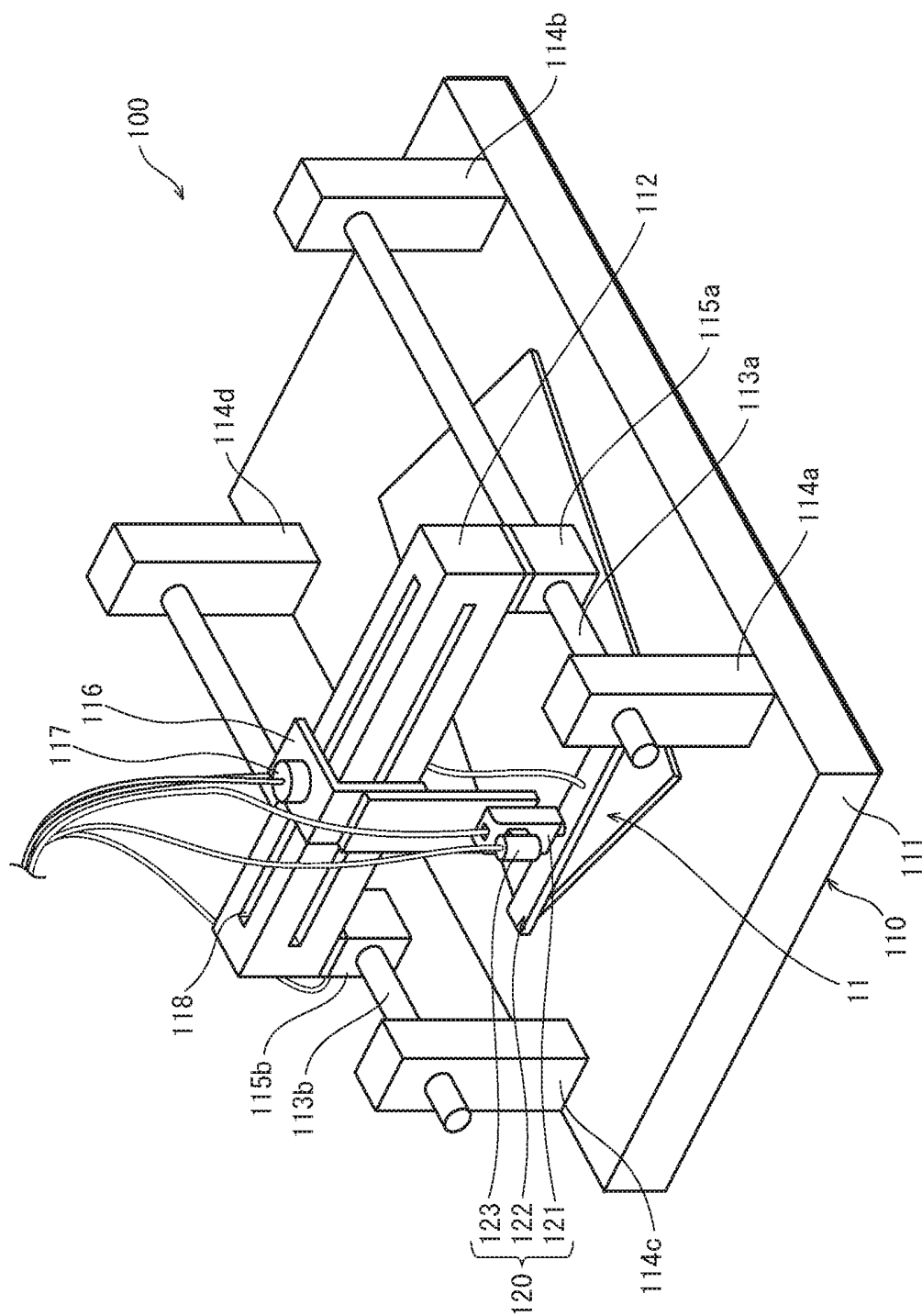
8
G
I
F

FIG. 9

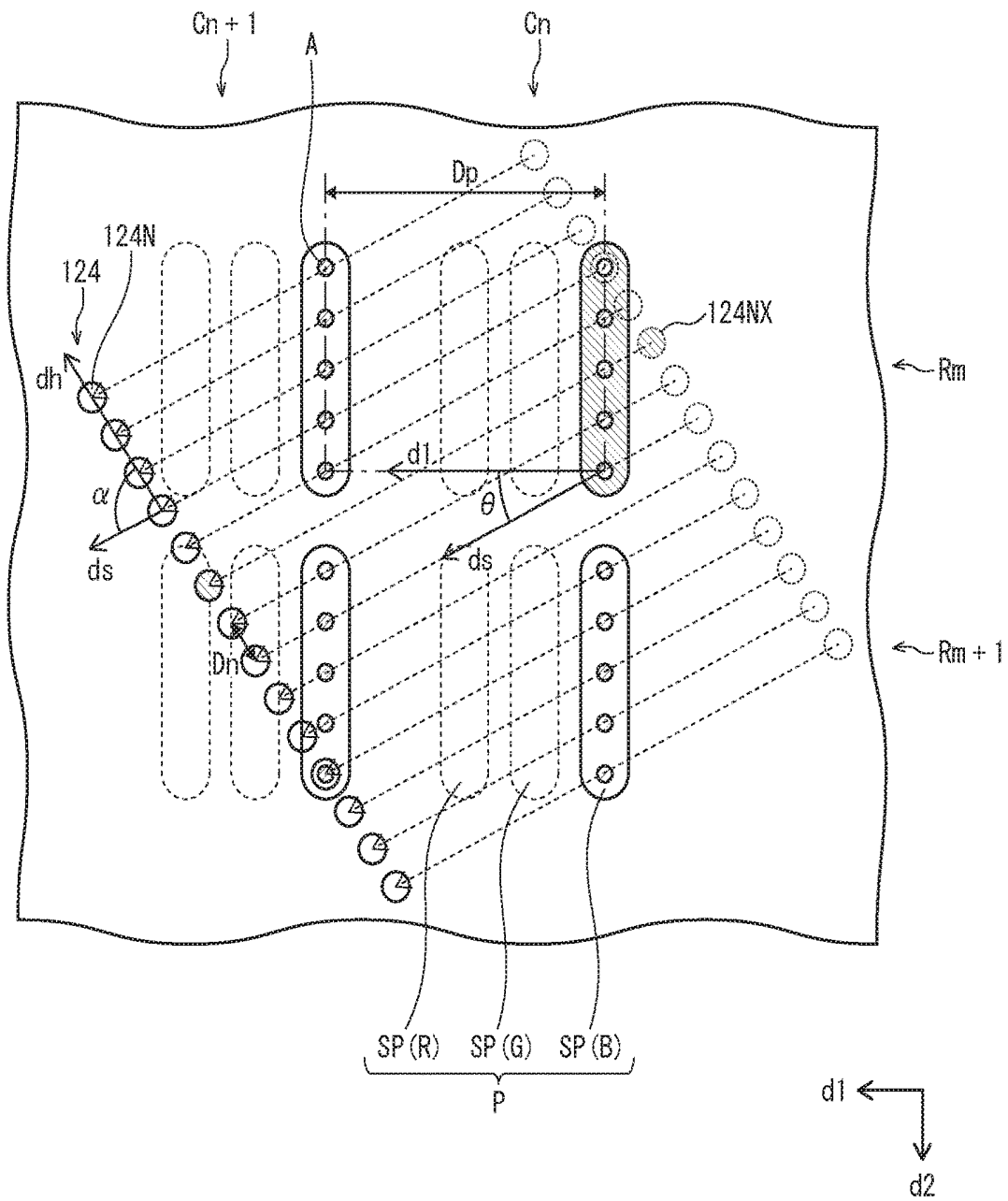


FIG. 10A

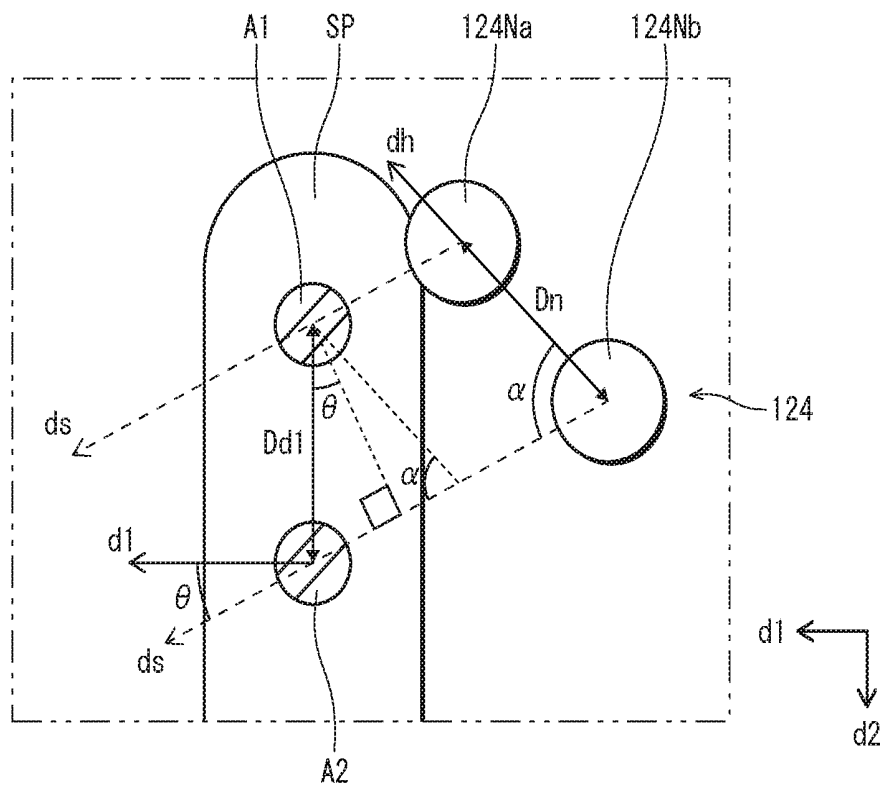


FIG. 10B

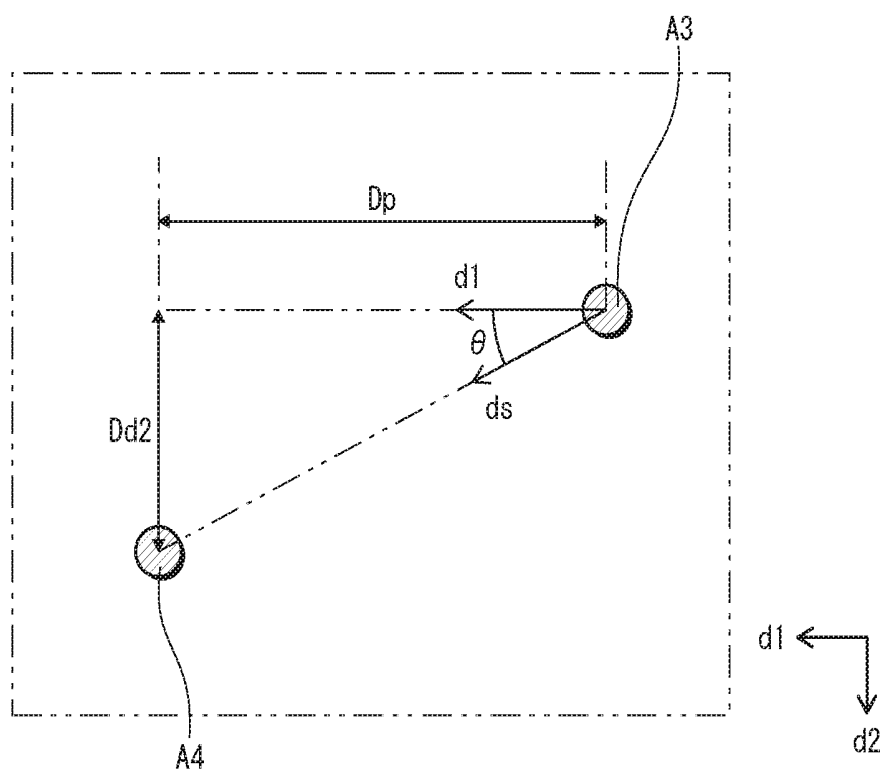


FIG. 11

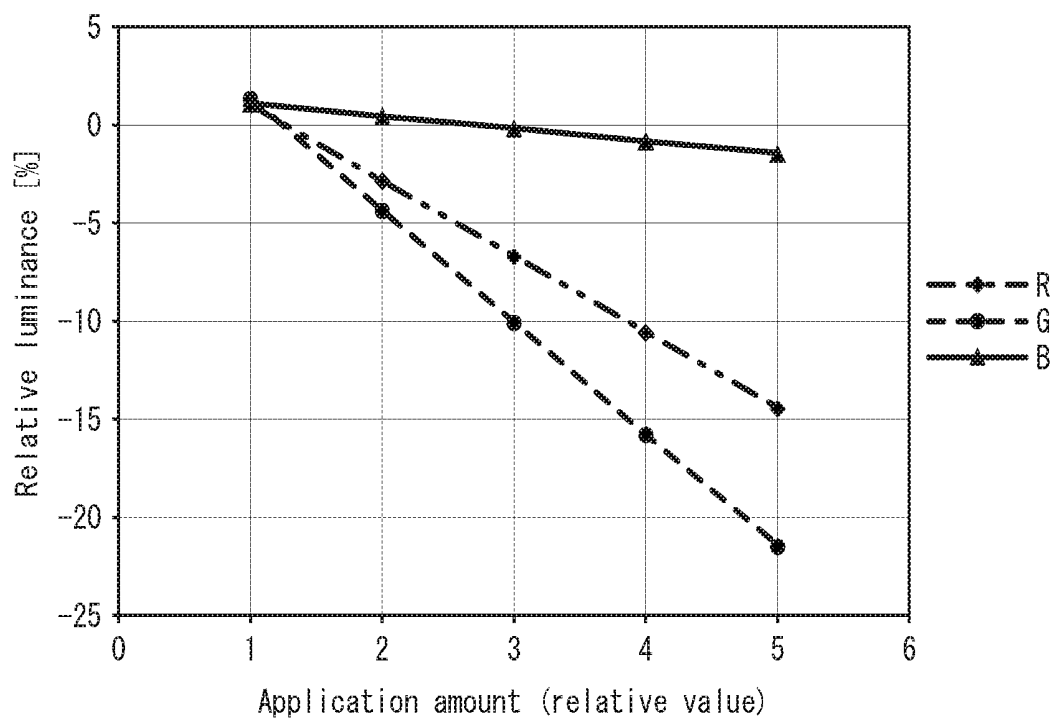


FIG. 12

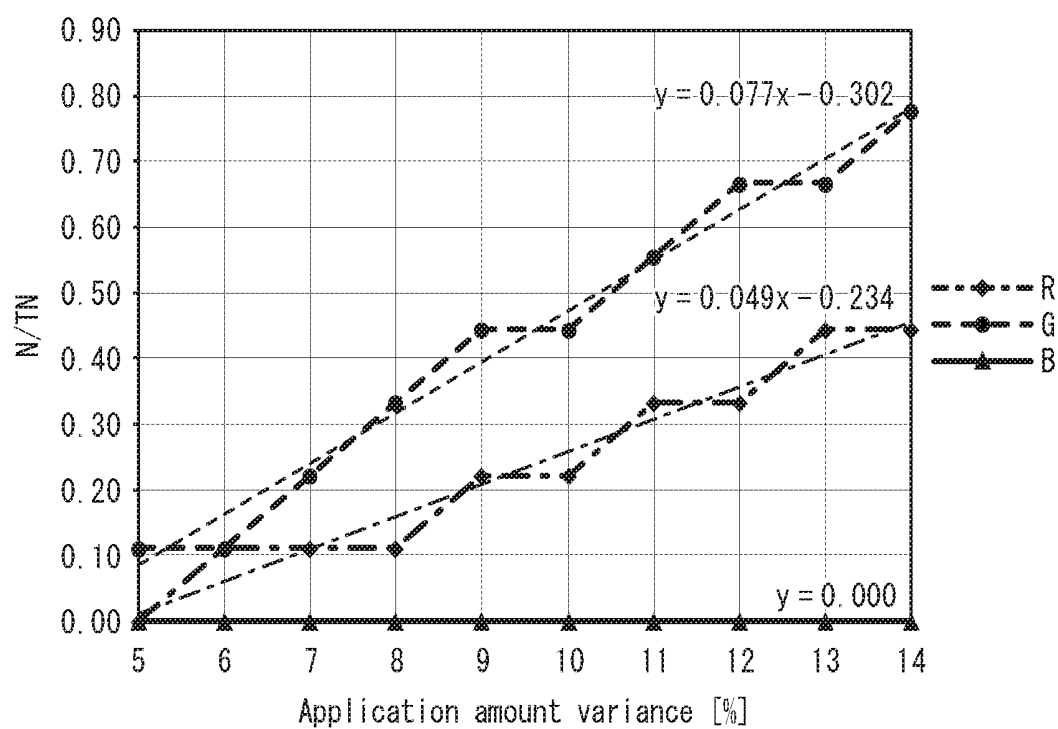


FIG. 13

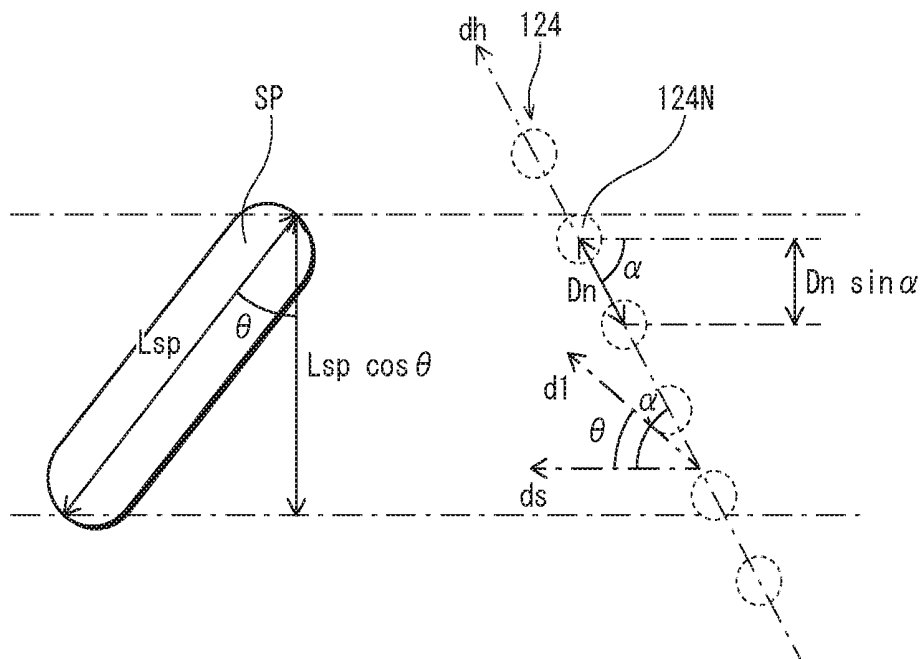


FIG. 14

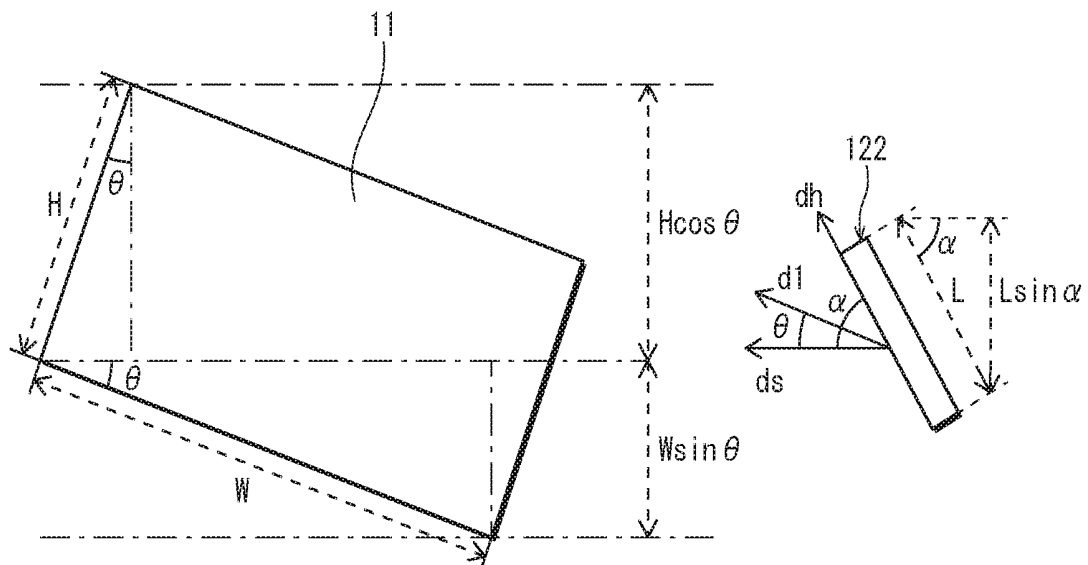


FIG. 15

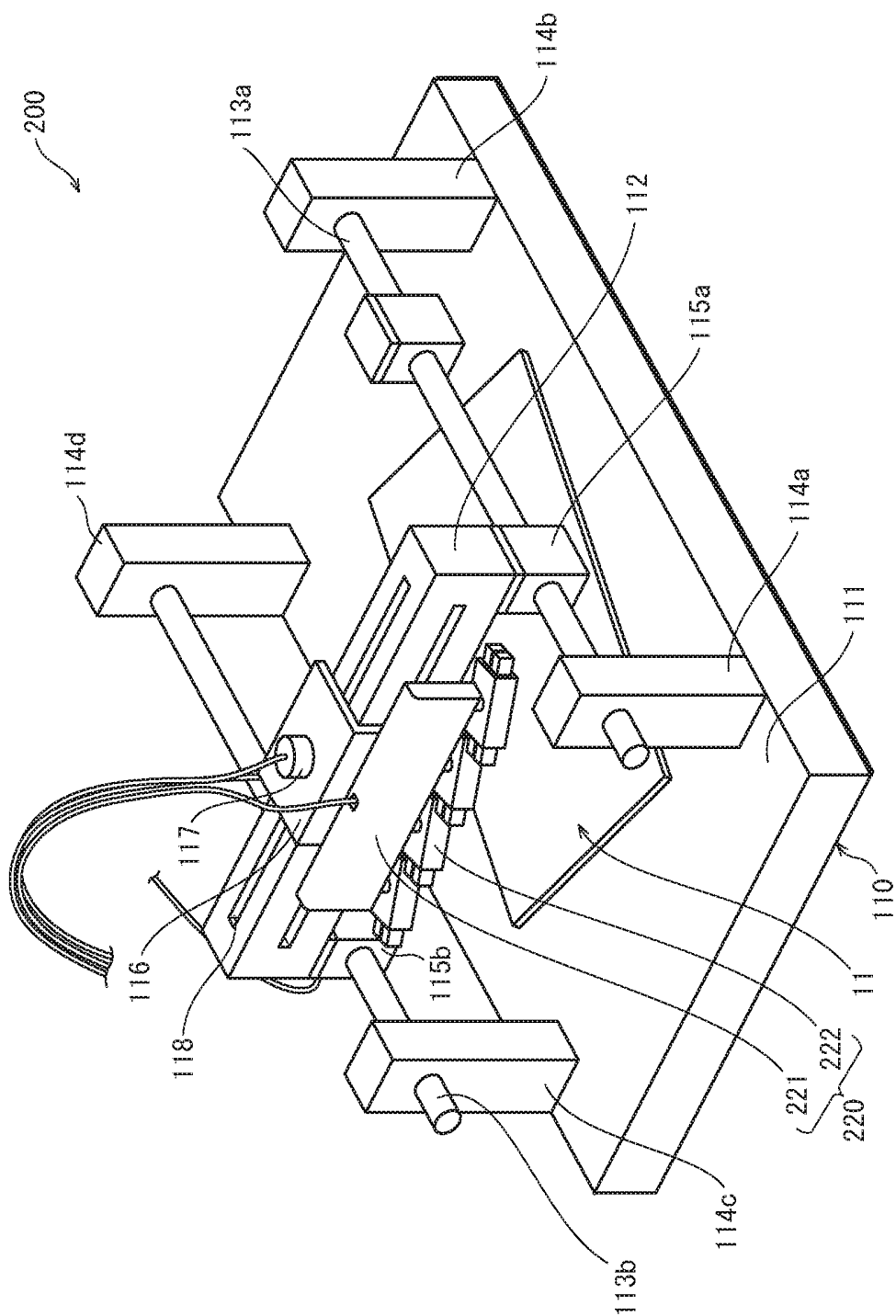


FIG. 16

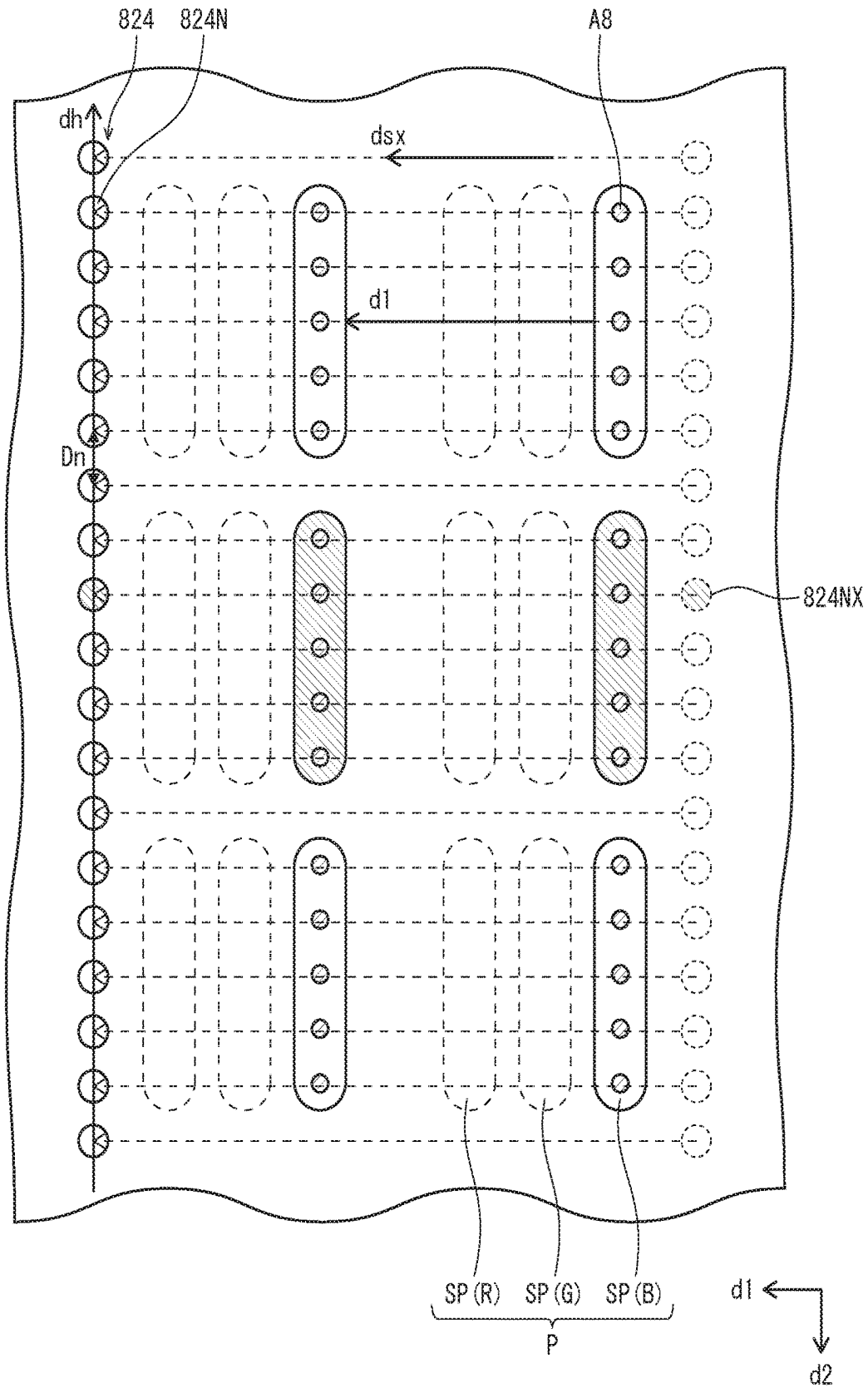
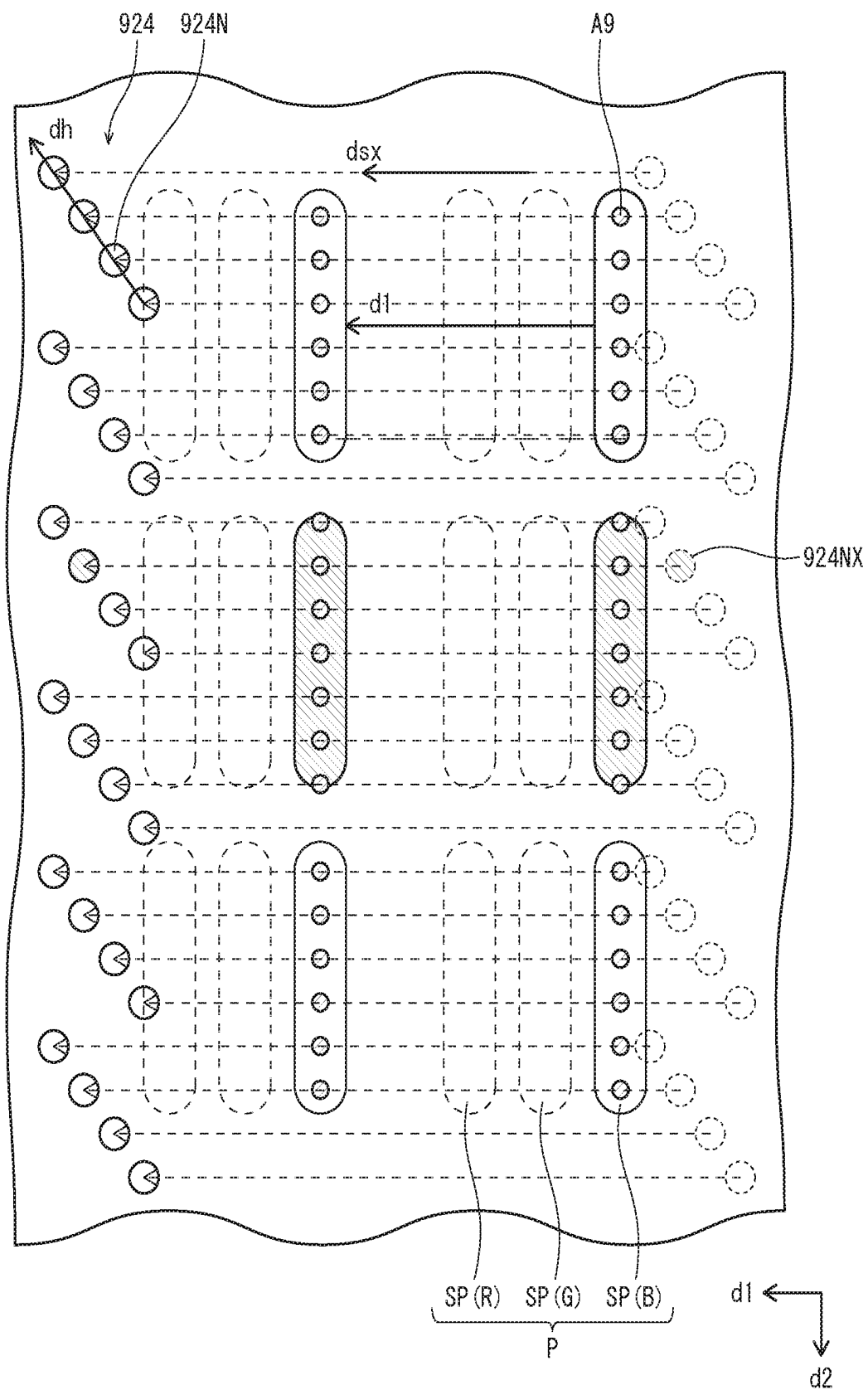


FIG. 17



ORGANIC EL DISPLAY PANEL
PRODUCTION METHOD

RELATED APPLICATIONS

This application is the U.S. National Phase under 35 U.S.C. § 371 of International Patent Application No. PCT/JP2015/001781, filed on Mar. 27, 2015, which in turn claims the benefit of Japanese Application No. 2014-081099, filed on Apr. 10, 2014, the disclosures of which Applications are incorporated by reference herein.

TECHNICAL FIELD

The present disclosure relates to a manufacturing method of an organic electroluminescence (EL) display panel, and particularly relates to a manufacturing method using a wet process.

BACKGROUND ART

In recent years, research and development are in progress of large-sized organic EL display panels using organic EL elements. In a typical organic EL display panel, a plurality of organic EL elements are arranged in a matrix along a main surface of a substrate serving as a support member, and an image is displayed on an image display face by the organic EL elements forming pixels.

In an organic EL element, one or more functional layers, including at least a light-emitting layer containing an organic compound, are sandwiched between a pair of electrodes. The functional layer may also include layers other than the light-emitting layer, such as an injection layer, a transport layer, a blocking layer, and a buffer layer. Formation methods for functional layers are broadly categorized into dry processes such as vacuum vapor deposition, and wet processes such as inkjet application. Wet processes involve use of a solution (hereinafter termed “ink”) containing functional layer material (functional material), and are considered to be suitable for the enlargement of display panels in terms of formation precision and cost. Particularly, development is in progress of inkjet application, which is a method where ink in the form of fine droplets is discharged to be directly applied to pixel formation regions on a substrate.

Ink application involves discharging ink to pixel formation regions on a substrate from a plurality of nozzles lining up in a straight line, while displacing the nozzles relative to the substrate in a predetermined scanning direction along a main surface of the substrate. Typically, the scanning direction is set to be parallel to either a row direction or a column direction of a matrix made up of the pixel formation regions. In addition, a technology is disclosed of adjusting the distance between application positions corresponding to adjacent nozzles by inclining the nozzle array direction relative to the scanning direction (see, for example, Patent Document 1).

CITATION LIST

Patent Literature

[Patent Literature 1]

Japanese Patent Application Publication No. 2004-111074

SUMMARY OF INVENTION

Technical Problem

FIG. 16 is a schematic plan view diagram illustrating a scanning direction dsx and application positions A8 of a nozzle array 824. The nozzle array 824 is composed of a plurality of nozzles 824N arranged to line up in an extension direction dh . Each nozzle 824N discharges ink in the form of fine droplets. FIG. 16 also illustrates pixel formation regions P, each including sub-pixel formation regions SP(R), SP(G), and SP(B). The pixel formation regions P are arranged in a row direction $d1$ and a column direction $d2$. The nozzles 824N are moved in a scanning direction dsx parallel to the row direction $d1$, while each nozzle 824N is caused to discharge ink to application positions A8 in sub-pixel formation regions SP(R), sub-pixel formation regions SP(G), or sub-pixel formation regions SP(B). FIG. 16 illustrates an example where each nozzle 824N discharges ink to application positions A8 in sub-pixel formation regions SP(B).

Here, different ones of the nozzles 824N may discharge different amounts of ink droplets. This is for example due to individual ink discharge mechanisms not being completely the same and due to ink discharge mechanisms not being in the same state after chronological change. With the method of FIG. 16, this difference in discharge amounts of the nozzles 824N is reflected in the row direction $d1$.

In the following, a specific example is considered, where a nozzle 824NX emphasized with diagonal hatching in FIG. 16 has an extremely small (or extremely great) discharge amount compared to the rest of the nozzles 824N. Because the scanning direction dsx is parallel to the row direction $d1$, sub-pixel formation regions SP(B) (emphasized with diagonal hatching in FIG. 16) lining up in the row direction $d1$ receive ink from the nozzle 824NX. Due to this, in an organic EL display panel manufactured using this method, faulty pixels line up in the row direction $d1$, and thus, the organic EL display panel exhibits a linear unevenness in luminance, light-emission color, etc., along a pixel arrangement direction. For example, the faulty pixels may be pixels having extremely high (or extremely low) luminance compared to other pixels, pixels not emitting any light, or pixels emitting a color not matching the desired color.

This linear unevenness in luminance, light-emission color, etc., along a pixel arrangement direction also occurs in an organic EL display panel manufactured using the method disclosed in Patent Literature 1. FIG. 17 is a schematic plan view diagram illustrating a scanning direction dsx and application positions A9 of nozzle arrays 924. Each nozzle array 924 is composed of a plurality of nozzles 924N arrayed to line up in an extension direction dh , which is inclined relative to the scanning direction dsx . Thus, the method illustrated in FIG. 17 is similar to the method disclosed in Patent Literature 1. However, the methods illustrated in FIGS. 16 and 17 are similar in that the scanning direction dsx is parallel to the row direction $d1$. Thus, for example, when there is a nozzle 924NX (emphasized with diagonal hatching in FIG. 17) having an extremely small (or extremely great) discharge amount compared to the rest of the nozzles 924N, sub-pixel formation regions SP(B) (emphasized with diagonal hatching in FIG. 17) lining up in the row direction receive ink from the nozzle 924NX. Due to this, an organic EL display panel that is manufactured using this method exhibits a linear unevenness in luminance, light-emission color, etc., along a pixel arrangement direc-

tion, similar to the organic EL display panel manufactured using the method illustrated in FIG. 16.

Furthermore, such linear unevenness in luminance, light-emission color, etc., not only occurs when a nozzle having an extremely different discharge amount are present (e.g., when the nozzles 824NX and 924NX are present). That is, even when the difference among nozzles is not so great, a linear unevenness in luminance, light-emission color, etc., along a pixel arrangement direction can occur when a group of nozzles differing from the rest of the nozzles in a similar manner are gathered within a certain area (e.g., nozzles whose discharge amounts are smaller than average are located adjacent to one another). When such a group of nozzles exists, the difference between these nozzles and the rest of the nozzles accumulates and produces a linear unevenness in luminance, light-emission color, etc., along a pixel arrangement direction.

Such a linear unevenness in luminance, light-emission color, etc., along one pixel arrangement direction is problematic for being very noticeable and bringing about a decrease in display quality of an organic EL display panel. In view of the above, the present invention aims to provide an organic EL display panel manufacturing method that uses inkjet application and that reduces the risk of occurrence of a linear unevenness in luminance, light-emission color, etc., along a pixel arrangement direction, caused by a difference in discharge amounts of nozzles.

Solution to Problem

One aspect of the present invention is a method for manufacturing an organic EL display panel, the method including: preparing a substrate; forming a plurality of first electrodes over the substrate; defining, above the substrate, a plurality of pixel formation regions lining up in a row direction and a column direction to form a matrix, by forming banks over the substrate having the first electrodes formed thereon; applying ink containing functional material to each of the pixel formation regions by causing a plurality of nozzles lining up in a straight line to discharge the ink to the pixel formation regions while displacing the nozzles relative to the substrate in a scanning direction along a main surface of the substrate; drying the ink having been applied to form functional layers containing the functional material in the pixel formation regions; and forming one or more layers, at least including a second electrode, at a position covering the pixel formation regions having the functional layers formed therein, wherein in the application of ink, an angle θ between the scanning direction and the row direction is set to more than 0° and less than 90° and each of the nozzles applies the ink across a plurality of rows of the pixel formation regions.

Advantageous Effects of Invention

In the method pertaining to one aspect of the present invention, the scanning direction in which the nozzles are displaced is inclined with respect to the row direction. Thus, even if the nozzles include a nozzle having a discharge amount smaller or greater than the rest of the nozzles, pixel formation regions receiving ink from the nozzle do not line up in the row direction and instead, the nozzle applies the ink across multiple rows of the pixel formation regions. Accordingly, the method pertaining to one aspect of the present invention reduces the risk of occurrence of a linear unevenness in luminance, light-emission color, etc., along the row

direction (i.e., a pixel arrangement direction), caused by a difference in discharge amounts of nozzles.

BRIEF DESCRIPTION OF DRAWINGS

FIG. 1 is a block diagram illustrating the overall configuration of an organic EL display device 1.

FIG. 2 is a schematic plan view of a magnified portion of an image display face of the organic EL display panel 10.

FIG. 3 is a schematic cross-sectional diagram of a sub-pixel formation region SP, taken along row direction d1.

FIG. 4 is a process diagram describing a manufacturing method of the organic EL display panel 10.

FIGS. 5A, 5B, and 5C are schematic cross-sectional diagrams illustrating manufacturing processes of the organic EL display panel 10, where FIG. 5A illustrates an anode formation process, FIG. 5B illustrates a hole injection layer formation process, and FIG. 5C illustrates a bank formation process.

FIGS. 6A, 6B, and 6C are schematic cross-sectional diagrams illustrating manufacturing processes of the organic EL display panel 10, where FIG. 6A illustrates an ink application process, FIG. 6B illustrates a drying process, and FIG. 6C illustrates an electron transport layer formation process.

FIGS. 7A and 7B are schematic cross-sectional diagrams illustrating manufacturing processes of the organic EL display panel 10, where FIG. 7A illustrates a cathode formation process and FIG. 7B illustrates a sealing process.

FIG. 8 is a perspective view diagram illustrating an inkjet device 100 used for applying ink 16a.

FIG. 9 is a schematic plan view diagram illustrating a scanning direction ds and application positions A of a nozzle array 124.

FIG. 10A is a diagram illustrating pitch Dd1 between application positions corresponding to adjacent nozzles 124Na and 124Nb, and FIG. 10B is a diagram illustrating an offset Dd2 in a column direction d2, between nozzle application positions A3 and A4 in adjacent pixel formation regions P.

FIG. 11 shows graphs indicating the relationship between application amount and relative luminance, for samples of the ink 16a.

FIG. 12 shows graphs indicating the relationship between application amount variance and N/TN, for samples of the ink 16a.

FIG. 13 is a schematic plan view diagram illustrating scanning of sub-pixel formation regions SP with the nozzle array 124 and with angles θ and α .

FIG. 14 is a schematic plan view diagram describing a scan count of the inkjet device 100.

FIG. 15 is a perspective view diagram illustrating an inkjet device 200 pertaining to a modification.

FIG. 16 is a schematic plan view diagram illustrating a scanning direction dsx and application positions A8 of a nozzle array 824.

FIG. 17 is a schematic plan view diagram illustrating a scanning direction dsx and application positions A9 of nozzle arrays 924.

DESCRIPTION OF EMBODIMENTS

Overview of Aspects of Present Invention

One aspect of the present invention is a method for manufacturing an organic EL display panel, the method including: preparing a substrate; forming a plurality of first

electrodes over the substrate; defining, above the substrate, a plurality of pixel formation regions lining up in a row direction and a column direction to form a matrix, by forming banks over the substrate having the first electrodes formed thereon; applying ink containing functional material to each of the pixel formation regions by causing a plurality of nozzles lining up in a straight line to discharge the ink to the pixel formation regions while displacing the nozzles relative to the substrate in a scanning direction along a main surface of the substrate; drying the ink having been applied to form functional layers containing the functional material in the pixel formation regions; and forming one or more layers, at least including a second electrode, at a position covering the pixel formation regions having the functional layers formed therein, wherein in the application of ink, an angle θ between the scanning direction and the row direction is set to more than 0° and less than 90° and each of the nozzles applies the ink across a plurality of rows of the pixel formation regions.

In the manufacturing method pertaining to one aspect of the present invention, the scanning direction in which the nozzles are displaced is inclined with respect to the row direction. Thus, even if the nozzles include a nozzle having a discharge amount smaller or greater than that of the rest of the nozzles, pixel formation regions receiving ink from the nozzle do not line up in the row direction and instead, the nozzle applies the ink across multiple rows of the pixel formation regions. Accordingly, the method pertaining to one aspect of the present invention reduces the risk of occurrence of a linear unevenness in luminance, light-emission color, etc., along the row direction (i.e., a pixel arrangement direction), caused by a difference in discharge amounts of nozzles.

Another aspect of the present invention is the method pertaining to one aspect of the present invention, wherein the pixel formation regions are defined to be located at a fixed pitch Dp in the row direction and at a fixed pitch $Dp2$ in the column direction, and in the application of ink, the angle θ is set to satisfy $Dp \times \tan \theta \neq Dp2$.

According to the method pertaining to this aspect, the combination of nozzles performing application changes from pixel formation region to pixel formation region. Thus, the risk is reduced of occurrence of a linear unevenness in luminance, light-emission color, etc., along the scanning direction.

Another aspect of the present invention is the method pertaining to one aspect of the present invention, wherein in the application of ink, the angle θ is set to satisfy:

$$\theta = \sin^{-1} \left(\frac{N \cdot Dn \cdot \sin \alpha}{Dp} \right) \quad [\text{Math. 1}]$$

where Dn denotes a fixed pitch between the nozzles, α denotes an angle between the scanning direction and the straight line, and N is a positive integer.

According to the method pertaining to this, ink application positions corresponding to the nozzles are offset by exactly N times the ink application pitch, between pixel formation regions adjacent in the row direction. Accordingly, ink application positions remain the same in all pixel formation regions lining up in the row direction. Thus, the risk is low of positions in the column direction, numbers, etc., of application positions differing among pixel formation regions P lining up in the row direction. Thus, the risk is reduced of occurrence of application unevenness along the

row direction. Accordingly, the method pertaining to this aspect reduces the risk of occurrence of unevenness in luminance, light-emission color, etc., in the row direction.

Another aspect of the present invention is the method pertaining to one aspect of the present invention, wherein the pixel formation regions are defined to each include sub-pixel formation regions corresponding to colors red, green, and blue, ink application with the nozzles is performed separately, by using different inks, for sub-pixel formation regions corresponding to the color red, sub-pixel formation regions corresponding to the color green, and sub-pixel formation regions corresponding to the color blue, and the positive integer N for angle θ defining the scanning direction in application of one of the inks with which luminance is most dependent upon application amount is no smaller than the positive integer N for angle θ defining the scanning direction in application of each of the other ones of the inks.

According to the method pertaining to this aspect, N denoting the number of nozzles performing application that are replaced is greatest in the application of an ink for which the influence of the difference in discharge amounts of nozzles with respect to luminance is relatively great. Accordingly, the method pertaining to this aspect effectively reduces the risk of occurrence of a linear unevenness in luminance, light-emission color, etc.

Another aspect of the present invention is the method pertaining to one aspect of the present invention, wherein the sub-pixel formation regions are each elongated in a direction orthogonal to the row direction, and in the application of any of the inks, the angle θ defining the scanning direction is set to more than 0° and less than 45° .

According to the method pertaining to this aspect, the scanning direction of the nozzles is relatively close to the row direction, which is orthogonal to the major axis direction of the sub-pixel formation regions. Accordingly, the method pertaining to this aspect increases the number of nozzles used for application per sub-pixel formation region, and thus, relatively reduces the influence of the difference in discharge amounts of the nozzles.

Another aspect of the present invention is the method pertaining to one aspect of the present invention, wherein in the application of any of the inks, the angle θ defining the scanning direction is set to satisfy:

$$\theta \leq \tan^{-1} \left(\frac{Lsp}{Dp} \right) \quad [\text{Math. 2}]$$

where Lsp denotes the length of the sub-pixel formation regions in the direction orthogonal to the row direction.

In the method pertaining to this aspect, the angle θ is set to a relatively large angle, and thus, the risk is reduced of problems occurring such as an increase in the number of nozzles required to perform application with respect to all of the sub-pixel formation regions, and the influence of the difference in discharge amounts of the nozzles appearing in the column direction.

Another aspect of the present invention is the method pertaining to one aspect of the present invention, wherein in the application of any of the inks, the angles θ and α defining the scanning direction are set to satisfy:

$$\alpha \leq 90^\circ - \theta \quad [\text{Math. 3}]$$

The method pertaining to this aspect ensures that the number of nozzles used for application per sub-pixel formation region is at least equal to the same in typical inkjet

application, and thus, reduces the risk of occurrence of a linear discrepancy in luminance, light-emission color, etc., without increasing unevenness in luminance among pixels.

Another aspect of the present invention is the method pertaining to one aspect of the present invention, wherein the main surface of the substrate has a rectangular shape, the pixel formation regions are defined so that the row direction matches a direction in which long sides of the substrate extend and the column direction matches a direction in which short sides of the substrate extend, and in the application of any of the inks, the angle θ defining the scanning direction is set to satisfy:

$$\left[\frac{H \cos \theta + W \sin \theta}{L \sin \alpha} \right] = \left[\frac{H}{L \sin \alpha} \right] \quad [\text{Math. 4}]$$

where W denotes a length of the long sides of the substrate, H denotes a length of the short sides of the substrate, and L denotes a length of the array of the nozzles.

The method pertaining to this aspect achieves applying ink to the entire surface of the substrate without increasing the number of scans that need to be performed from that in typical inkjet application. Thus, the method pertaining to this aspect prevents an increase in manufacturing procedures.

Note that in the present disclosure, an angle between two intersecting directions is to be construed as the smaller one among the angles formed by the two directions when projected onto a plane defined by the two directions. Accordingly, an angle between two directions is no less than 0° and no more than 90°.

Embodiment

The following describes an organic EL display panel manufacturing method pertaining to one aspect of the present invention, with reference to the accompanying drawings.

1. Overall Configuration of Organic EL Display Device 1

FIG. 1 is a block diagram illustrating the overall configuration of an organic EL display device 1. The organic EL display device 1 is used in a device such as television, a personal computer, an industrial display, or a portable terminal, and includes an organic EL display panel 10 having a rectangular shape and a drive control unit 20 connected to the organic EL display panel 10. The drive control unit 20 includes four drive circuits, namely drive circuits 21, 22, 23, 24, and a control circuit 25.

The organic EL display panel 10 (referred to in the following as a panel 10) has a rectangular image display face. For example, the display panel 10 is a top-emission-type organic EL display panel using the active matrix scheme in the embodiment. In FIG. 1, four drive circuits, namely drive circuits 21, 22, 23, 24 are arranged surrounding the panel 10. However, the drive control unit 20 need not have the configuration illustrated in FIG. 1, and the quantity, the positions, etc., of the drive circuits may be changed as appropriate.

2. Configuration of Panel 10

FIG. 2 is a schematic plan view of a magnified portion of the image display face of the panel 10. The panel 10 has a plurality of pixel formation regions P. The pixel formation regions P are arranged in a matrix, defined by row direction d1 and column direction d2 that are orthogonal directions along the image display face. In row direction d1, pixel

formation regions P line up at a fixed pitch Dp, and in column direction d2, pixel formation regions line up at a fixed pitch Dp2.

Each pixel formation region P is a set of one sub-pixel formation region SP(R), one sub-pixel formation region SP(G), and one sub-pixel formation region SP(B) that are arranged in row direction d1 while being spaced away from one another in row direction d1. The sub-pixel formation region SP(R), the sub-pixel formation region SP(G), and the sub-pixel formation region SP(B) respectively correspond to the colors red (R), green (G), and blue (B). In the following, wherever it is unnecessary to distinguish the sub-pixel formation regions of the different colors (i.e., the sub-pixel formation regions SP(R), SP(G), SP(B)) from one another, the sub-pixel formation regions are referred to as sub-pixel formation regions SP.

As illustrated in FIG. 1, row direction d1 is parallel to a direction in which long sides of the panel 10 extend (referred to in the following as a long-side direction), and row direction d2 is parallel to a direction in which short sides of the panel 10 extend (referred to in the following as a short-side direction). In the present disclosure, a short-side direction of a rectangle or a rectangular-shaped object refers to a direction orthogonal to a long-side direction of the same.

FIG. 3 is a schematic cross-sectional diagram of one sub-pixel formation region SP, taken along row direction d1. A top-emission-type organic EL element is disposed at the sub-pixel formation region SP. The organic EL element includes a substrate 11 and layers stacked over the substrate 11, which include a first electrode 12, a light-transmissive electrode 13, a hole injection layer 14, banks 15, a light-emitting layer 16, an electron transport layer 17, a second electrode 18, and a sealing layer 19. This list of layers stacked over the substrate 11 is a mere example, and one or more other layers, such as a hole transport layer, an electron injection layer, a blocking layer, and/or a buffer layer, may also be stacked over the substrate 11. Also, one or more of the layers in the list above may not be included.

When the panel 10 is seen as a whole, a plurality of first electrodes 12 are arranged in the row direction d1 and the column direction d2 to form a matrix, and one light-transmissive electrode 13 is disposed on each of the first electrodes 12. Further, one hole injection layer 14 is disposed to cover the top surface of the substrate 11 and all of the light-transmissive electrodes 13. The hole injection layer 14 has disposed thereon banks 15. The banks 15 define apertures 15a. The apertures 15a define the pixel formation regions P and the sub-pixel formation regions SP. One light-emitting layer 16 is disposed in each aperture 15a. Furthermore, one electron transport layer 17, one second electrode 18, and one sealing layer 19 are disposed in the stated order. Each of these layers covers all of the light-emitting layers 16 and the banks 15 between the light-emitting layers 16. Note that the structure of the panel 10 described above is a mere example, and for example, layers such as the hole injection layer 14, the electron transport layer 17, and the second electrode 18 may be disposed only within the apertures 15a.

Further, although not illustrated in any of the drawings, a plurality of first electrodes 12 may be disposed along the column direction d2 within each of the apertures 15a defined by the banks 15, so that at each sub-pixel formation region SP, a plurality of first electrodes 12 are arranged along the column direction d2. For example, in each aperture 15a, three first electrodes 12 may be disposed along the column direction d2. When making this modification, the three first electrodes 12 may be separately controlled by using separate

signals, or the three first electrodes **12** may be controlled by using a single signal. In particular, when controlling the three first electrodes **12** separately by using separate signals, a pixel definition layer composed of an electrical insulator may be disposed between adjacent first electrodes **12** to avoid interference between the adjacent first electrodes **12**. When making this modification, it is preferable that the pixel definition layer have a height lower than the height of the banks **15**.

The substrate **11** serves as a support of the panel **10**. Although not illustrated in any of the drawings, the substrate **11** includes a main body having a rectangular plate-like shape and a thin film transistor (TFT) layer disposed on the main body. The TFT layer includes electronic circuit elements such as TFT elements, capacitor elements, and wiring. The electronic circuit elements in the TFT layer form circuits that supply organic EL elements with current. Also, the TFT layer has, at a top-most portion thereof, an interlayer electrical insulation layer (not depicted) planarizing the top surface of the substrate **11**.

The main body of the substrate is formed by using an electrically-insulative material. For example, the material may be soda glass, nonfluorescent glass, phosphate glass, borate glass, quartz, acrylic resin, styrenic resin, polycarbonate resin, epoxy resin, polyethylene, polyester, silicone resin, or alumina. Alternatively, the main body of the substrate **11** may be a plate of a metal, such as aluminum or stainless steel, coated with an electrically-insulative material.

The TFT layer of the substrate **11** includes a laminate structure and the interlayer electrical insulation layer, which covers the laminate structure. The laminate structure includes a semiconductor, an electrical conductor, and an electrical insulator that form various elements and wiring. For example, the semiconductor may be an oxide semiconductor such as indium gallium zinc oxide (IGZO) or an organic semiconductor having a conjugated, planar π electron system, such as a heteroaromatic compound. For example, the electrical conductor may be a metal such as aluminum, copper, or gold, or an electrically conductive oxide such as indium tin oxide (ITO) or indium zinc oxide (IZO). For example, the electrical insulator may be silicon nitride, silicon oxide, silicon oxynitride, aluminum oxide, acrylic resin, polyimide resin, siloxane resin, or phenolic resin. The interlayer electrical insulation layer is formed by using a material that is electrically insulative and that can be patterned. For example, the interlayer electrical insulation layer may be formed by using an organic material such as acrylic resin, polyimide resin, siloxane resin, or phenolic resin.

In the panel **10**, the substrate **11** (main body) defines the long-side direction and the short-side direction of the panel **10**. Accordingly, the long-side direction and the short-side direction of the main surface of the substrate **11** (main body) are parallel to the row direction **d1** and the column direction **d2**, respectively.

The first electrodes **12** are formed by using, for example, aluminum (Al), silver (Ag), APC (alloy of silver, palladium, and copper), ARA (alloy of silver, rubidium, and gold), MoCr (alloy of molybdenum and chromium), or NiCr (alloy of nickel and chromium). Not only do the first electrodes **12** function as parts of anodes, the first electrodes **12** also have the function of reflecting visible light generated in the light-emitting layers **16** and guiding the visible light upwards.

The light-transmissive electrodes **13** are formed by using, for example, ITO or IZO. Not only do the light-transmissive

electrodes **13** function as parts of anodes, the light-transmissive electrodes **13** have the function of improving the adhesion between the first electrodes **12** and the hole injection layer **14** by being disposed therebetween.

For example, the hole injection layer **14** is formed by using a metal compound such as a metal oxide, a metal nitride, or a metal oxynitride. For example, metal oxides usable for forming the hole injection layer **14** include oxides of metals such as chromium (Cr), molybdenum (Mo), tungsten (W), vanadium (V), niobium (Nb), tantalum (Ta), titanium (Ti), zircon (Zr), hafnium (Hf), scandium (Sc), yttrium (Y), thorium (Th), manganese (Mn), iron (Fe), ruthenium (Ru), osmium (Os), cobalt (Co), nickel (Ni), copper (Cu), zinc (Zn), cadmium (Cd), aluminum (Al), gallium (Ga), indium (In), silicon (Si), germanium (Ge), stannum (Sn), lead (Pb), antimony (Sb), and bismuth (Bi), and oxides of so-called rare earth metals from lanthanum (La) to lutetium (Lu).

For example, the banks **15** are formed by using an organic material such as resin or an inorganic material such as glass. Examples of organic materials usable for forming the banks **15** include acrylic resin, polyimide resin, and novolac-type phenolic resin. Examples of inorganic material usable for forming the banks **15** include silicon oxide (SiO) and silicon nitride (SiN). As illustrated in FIG. 2, the banks **15** are formed so that the sub-pixel formation regions SP (apertures **15a**) have shapes similar to ellipsoids in plan view, having the column direction **d2** as a major axis and having the row direction **d1** as a minor axis. Specifically, the banks **15** define the apertures **15a** such that for each of the apertures **15a**, the opposing edges of the aperture **15a** in the row direction **d1** are linear, and the opposing edges of the aperture **15a** in the column direction **d2** are semi-circular arcs.

Referring to FIG. 3 once again, the light-emitting layers **16** are formed by using, for example, F8BT (Poly(9,9-di-n-octylfluorene-alt-benzothiadiazole)), which is an organic high polymer. Alternatively, a conventional organic material other than F8BT may be contained in the light-emitting layers **16**. Examples of such materials include: a fluorescent material such as an oxinoid compound, perylene compound, coumarin compound, azacoumarin compound, oxazole compound, oxadiazole compound, perinone compound, pyrrolo-pyrrole compound, naphthalene compound, anthracene compound, fluorene compound, fluoranthene compound, tetracene compound, pyrene compound, coronene compound, quinolone compound, azaquinolone compound, pyrazoline derivative, pyrazolone derivative, rhodamine compound, chrysene compound, phenanthrene compound, cyclopentadiene compound, stilbene compound, diphenylquinone compound, styryl compound, butadiene compound, dicyanomethylene pyran compound, dicyanomethylene thiopyran compound, fluorescein compound, pyrylium compound, thiapyrylium compound, selenapyrylium compound, telluropirylium compound, aromatic aldadiene compound, oligophenylene compound, thioxanthene compound, cyanine compound, acridine compound, metal complex of a 8-hydroxyquinoline compound, metal complex of a 2-bipyridine compound, complex of a Schiff base and a group III metal, metal complex of oxine, rare earth metal complex, etc., as disclosed in Japanese Patent Application Publication No. H5-163488. In the present embodiment, the light-emitting layers **16** are described as one example of a functional layer.

The electron transport layer **17** is formed by using a material having the function of transporting, to the light-emitting layers **16**, electrons that the second electrode **18** injects into the electron transport layer **17**. Specifically, the

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electron transport layer **17** is formed by using, for example, a nitro-substituted fluorenone derivative, a thiopyran dioxide derivative, a diphenylquinone derivative, a perylene tetracarboxyl derivative, an anthraquinodimethane derivative, a fluoronylidene methane derivative, an anthrone derivative, an oxadiazole derivative, a perinone derivative, or a quinolone complex derivative, all of which are disclosed in Japanese Patent Application Publication No. H5-163488). Alternatively, the electron transport layer **17** may be formed by using a phosphorous oxide derivative, a triazole derivative, a triazine derivative, a silole derivative, a dimesitylboron derivative, or a triarylboron derivative.

The second electrode **18** is formed by using, for example, ITO or IZO, and functions as a cathode.

The sealing layer **19** has the function of preventing the second electrode **18** and layers therebelow from being exposed to moisture, air, and the like. For example, the sealing layer **19** is formed by using silicon nitride or silicon oxynitride.

3. Manufacturing Method of Organic EL Display Panel **10**
FIG. **4** is a process diagram describing a manufacturing method of the panel **10**. FIGS. **5A**, **5B**, **5C**, **6A**, **6B**, **6C**, **7A**, and **7B** are schematic cross-sectional diagrams illustrating manufacturing processes of the panel **10**.

(1) Substrate Preparation (S1)

First, the substrate **11** is prepared. Specifically, a main body formed by providing an electrically insulative material with a rectangular plate-like shape is prepared, and the TFT layer is formed on the main body. The TFT layer is formed, for example, through a combination of a thin-film formation method such as sputtering, chemical vapor deposition, or spin coating, and a patterning method such as photolithography. Also, processing such as plasma ion injection and baking may be performed in accordance with needs.

(2) Anode Formation (S2)

Next, anodes are formed on the substrate **11**. Each anode is a combination of one first electrode **12** and one light-transmissive electrode **13**. Specifically, a thin metal film is first formed through sputtering, for example, and then, the thin metal film is patterned into a matrix through photolithography (FIG. **5A**). Thus, the first electrodes **12** are formed on the substrate to form a matrix. Here, the thin metal film may also be formed through vacuum vapor deposition, for example. Then, in a similar manner, a thin ITO film is formed through sputtering, for example, and patterning is performed so that the thin ITO film remains on only the first electrodes **12** through photolithography, for example. Thus, the light-transmissive electrodes **13** are formed. Note that the first electrodes **12** and the transparent electrodes **13** forming a matrix on the substrate **11** may be formed by first forming the thin metal layer and the thin ITO layer, and then performing patterning first with respect to the thin ITO layer and then with respect to the thin metal layer through photolithography.

(3) Hole Injection Layer Formation (S3)

Next, the hole injection layer **14** is formed over the substrate **11** with the transparent electrodes **13** already formed thereon. Specifically, a tungsten oxide film having uniform thickness across the entire top surface of the substrate **11**, including the top surfaces of the transparent electrodes **13**, is formed through vacuum deposition or sputtering, for example (FIG. **5B**). Thus, the hole injection layer **14** is formed.

(4) Bank Formation (S4)

Next, the banks **15** are formed over the substrate **11** with the hole injection layer **14** already formed thereon. Specifically, a resist film containing a photoresist material is formed

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over the hole injection layer **14** through material application, for example, and then the apertures **15a** are formed in the resist layer at positions over the transparent electrodes **13** through photolithography, for example (FIG. **5C**). Thus, the banks **15** are formed. The apertures **15a** defined by the banks **15** form a matrix and each expose one of the transparent electrodes **13**. That is, the apertures **15a** define the sub-pixel formation regions SP. Further, the apertures **15a** are formed to define the pixel formation regions P, each of which being a set of three sub-pixel formation regions SP lining up in the row direction d1.

(5) Ink Application (S5)

Next, ink **16a** is applied onto the substrate **11** with the banks **15** already formed thereon. Specifically, the ink **16a**, which contains material for the light-emitting layers **16**, is applied to each of the apertures **15a** (sub-pixel formation regions SP) through inkjet application (FIG. **6A**). The details of the application of the ink **16a** are described later in the present disclosure.

(6) Drying (S6)

Next, the ink **16a** having been applied is dried. Specifically, the drying is performed by evaporating the solvent in the ink **16a** by placing the substrate **11** already having received the application of the ink **16a** in a vacuum environment (e.g., in a vacuum chamber). Accordingly, the light-emitting layer **16** is formed in each of the sub-pixel formation regions SP (FIG. **6B**).

(7) Electron Transport Layer Formation (S7)

Next, the electron transport layer **17** is formed at a position covering the sub-pixel formation regions SP having the light-emitting layers **16** formed therein. Specifically, a thin film of a material for the electron transport layer **17** is formed to cover the top surface of the layer structure already formed on the substrate **11** through vacuum vapor deposition, for example (FIG. **6C**). Thus, the electron transport layer **17** is formed.

(8) Cathode Formation (S8)

Next, a cathode is formed over the substrate **11** with the electron transport layer **17** already formed thereon. The cathode is composed of the second electrode **18**. Specifically, a thin ITO film is formed to cover the top surface of the layer structure already formed on the substrate **11** through sputtering, for example (FIG. **7A**). Thus, the second electrode **18** is formed. The second electrode **18** need only be formed at least at a position covering the sub-pixel formation regions SP having the light-emitting layers **16** formed therein.

(9) Sealing (S9)

Finally, the substrate **11** having the second electrode **18** already formed thereon is sealed. Specifically, a thin silicon nitride film is formed to cover the layer structure already formed over the substrate **11** through sputtering, for example (FIG. **7B**). Thus, the sealing layer **19** is formed. Additionally, after forming the sealing layer **19**, a sealing material with a plate-like shape may be adhered onto the top surface of the sealing layer **19** via an adhesive such as an organic resin. This sealing material may include, for example, color filters having the function of correcting light-emission color.

This completes the manufacturing of the panel **10**, which has organic EL elements formed in the sub-pixel formation regions SP. Note that the components of the panel **10** need not be formed by using the exemplary methods (e.g., film formation methods and patterning methods) described above. That is, the components may be formed through other methods.

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4. Application Method of Ink 16a

The following describes a method of applying the ink 16a through inkjet application, in the manufacturing method of the panel 10.

(1) Description of Inkjet Device 100

FIG. 8 is a perspective view diagram illustrating an inkjet device 100 used for applying the ink 16a. The inkjet device 100 includes, as main components thereof, a work table 110 and a head unit 120.

a. Work Table 110

The work table 110 is a so-called gantry table, and includes a base 111 and a moving frame 112. The base 111 holds an application target object (the substrate 11 in the present embodiment). The moving frame 112 is arranged over the base 111 and has an elongated shape.

The base 111 is a rectangular solid, and has a rectangular top surface on which the application target object is mounted. Hereinafter, the direction in which the long sides of the top surface of the base 111 extend is referred to as a long-side direction of the base 111, and the direction in which the short-sides of the top surface of the base 111 extend is referred to as a short-side direction of the base 111.

The moving frame 112 is suspended across a pair of guide shafts 113a and 113b arranged in parallel along the long-side direction of the base 111. The guide shafts 113a and 113b are supported by stands 114a, 114b, 114c, and 114d, which are columnar and disposed at four corners of the base 111.

The guide shafts 113a and 113b are respectively equipped with linear motor units 115a and 115b, enabling the moving frame 112 to move in the long-side direction of the base 111.

The moving frame 112 has a mount 116 having an L shape attached thereto. The mount 116 is equipped with a servomotor unit 117. The servomotor unit 117 enables the mount 116 to move in the short-side direction of the base 111 along a guide groove 118.

The linear motor units 115a and 115b and the servo motor unit 117 are connected to a control device (not depicted), and the movement of the moving frame 112 in the long-side direction and the movement of the mount 116 in the short-side direction are controlled by signals from the control device.

Also, in the inkjet device 100, the application target object on the base 11 can be fixed or rotated in a plane parallel to the top surface of the base 111. Thus, the orientation of the application target object relative to the top surface of the base 111 can be set as desired. This is achieved by providing, at a position on the base 111 where the application target object is mounted, a rotating table capable of switching between fixed state and freely rotatable state, for example.

b. Head Unit 120

The head unit 120 includes a main body 121, an inkjet head 122, and an imaging device 123. The main body 121 is fixed to the mount 116 of the work table 110. The inkjet head 122 and the imaging device 123 are attached to the main body 121.

While not illustrated in any of the drawings, the inkjet head 122 is an elongated member having, at a bottom surface thereof, a plurality of nozzles 124N (for example, about ten thousand nozzles 124N) lining up in a straight line in a long-side direction of the inkjet head 122. The nozzles 124N are spaced away from one another, disposed at a fixed nozzle pitch Dn. Accordingly, the nozzles 124N form a nozzle array 124 extending in an extension direction dh, which corresponds to the long-side direction of the inkjet head 122. The nozzles 124N each have a piezoelectric element (undepicted), a liquid chamber (undepicted) connected to the piezoelectric element, and a discharge outlet.

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When the piezoelectric element presses the liquid chamber, the ink 16a within the liquid chamber is discharged from the discharge outlet.

The main body 121 has a drive circuit (undepicted) for individually driving the piezoelectric elements of the nozzles 124N. The drive circuit is connected to the above-described control device, which provides a signal controlling discharge amount, discharge timing, and the like for each nozzle 124N. The main body 121 further includes a servomotor (undepicted) that is also connected to the control device. This servomotor is capable of causing the inkjet head 122 to rotate in a plane parallel to the top surface of the base 111 with the main body 121 as the rotation center. Accordingly, an angle α between the extension direction dh of the nozzle array 124 and the long-side direction of the base 111 (movement direction of the moving frame 112) can be controlled, and the relative distance of the nozzles 124N from the application target object, i.e., the application distance, can also be controlled.

The imaging device 123 is, for example, a CCD camera connected to the aforementioned control device. The imaging device 123 images a surface of the application target object and transmits image data so acquired to the control device. The control device is capable of judging whether or not to cause each of the nozzles 124N to discharge ink, based on the image data of the application target object transmitted from the imaging device 123. Thus, the nozzles 124N are capable of discharging the ink 16a with respect to only predetermined positions on the application target object.

Note that in the above-described structure, the nozzle array 124 is capable of moving in the long-side direction and the short-side direction of the base 111 due to being indirectly attached to the mount 116 and the moving frame 112 via the main body 121 of the head unit 120.

(2) Usage Method of Inkjet Device 100

For example, in the application of the ink 16a with the inkjet device 100, first the angle α between the extension direction dh of the nozzle array 124 and the long-side direction of the base 111 is set to a predetermined value, and then the application target object is placed on the base 111. Next, the orientation of the application target object relative to the top surface of the base 111 is set. Furthermore, the mount 116 is moved in the short-side direction of the base 111 in accordance with the angle α and the relative orientation of the application target object, to set an area of the application target object to be scanned with the nozzle array 124.

Then, the moving frame is moved to cause the nozzle array 124 to move (this movement of the nozzle array 124 is also referred to in the following as a "scan" by the nozzle array 124) in the long-side direction of the base 111, and the nozzles 124N are each caused to discharge the ink 16a to the application target object when arriving at predetermined positions over the application target object. Thus, for the inkjet device 100, the long-side direction of the base 111 corresponds to a scanning direction ds of the nozzle array 124. Also, due to this, the ink 16a is applied at predetermined positions of the application target object, over which the nozzle array 124 moves.

Note that when the ink 16a cannot be applied to all of the predetermined positions of the application target object through a single scan with the nozzle array 124, the nozzle array 124 is caused to perform another scan after the mount 116 is moved to cause the nozzle array 124 to move in the short-side direction of the base 111.

(3) Method of Applying Ink 16a to Substrate 11

The following describes a method of applying the ink 16a to the substrate 11 using the inkjet device 100.

FIG. 9 is a schematic plan view diagram illustrating the scanning direction ds of the nozzle array 124 and application positions A. FIG. 9 illustrates an example in which the ink 16a is applied to sub-pixel formation regions SP(B) of the pixel formation regions P. For ease of explanation, in the matrix formed by the four pixel formation regions P illustrated in FIG. 9, the ones of the pixel formation regions P illustrated in the upper side of page are considered as belonging to row Rm and the ones of the pixel formation regions P illustrated in the lower side of the page are considered as belonging to row Rm+1, and the ones of the pixel formation regions P illustrated in the right side of the page are considered as belonging to column Cn and the ones of the pixel formation regions P illustrated in the left side of the page are considered as belonging to column Cn+1.

The application of the ink 16a to the substrate 11 in the present embodiment takes advantage of the fact that the orientation of the application target object relative to the top surface of the base 111 can be changed with the inkjet device 100. Specifically, an angle θ between the row direction d1, which is one direction in which pixel formation regions P line up on the substrate 11, and the scanning direction ds of the nozzle array 124 is set to more than 0° and less than 90°.

When setting the angle θ in such a manner, the scanning direction ds is inclined by the angle θ relative to the row direction d1. FIG. 9 illustrates an example where the nozzle array 124 moves from the upper right of the page toward the lower left of the page. Also, the nozzles 124N apply the ink 16a to the exact row-direction centers of the sub-pixel formation regions SP. Accordingly, the application positions A of the ink 16a line up along the column direction d2.

When making such a configuration, even when for example the nozzle array 124 includes a nozzle 124NX having a discharge amount smaller or greater than that of the rest of the nozzles 124N in the nozzle array 124, the nozzle 124NX applies the ink 16a across multiple rows of sub-pixel formation regions SP, or in other words, the sub-pixel formation regions SP receiving the ink 16a from the nozzle 124NX do not line up in the row direction d1. Specifically, in FIG. 9, at the column Cn, the nozzle 124NX (emphasized with diagonal hatching) passes over and applies the ink 16a with respect to the sub-pixel formation region SP(B) belonging to row Rm (emphasized with diagonal hatching). Meanwhile, at column Cn+1, the nozzle 124NX arrives at the midpoint between row Rm and row Rm+1. This is since due to the angle θ , the arrival position of the nozzle 124NX at column Cn+1 is offset downwards in the column direction with respect to the arrival position of the nozzle 124NX at column Cn. Thus, at the column Cn+1, the nozzle 124NX does not apply the ink 16a with respect to the sub-pixel formation region SP(B) belonging to row Rm, and accordingly sub-pixel formation regions SP(B) receiving the ink 16a from the nozzle 124NX do not line up in the row Rm.

Here, the nozzle 124NX may pass over sub-pixel formation regions SP(B) in the same row Rm at both column Cn and column Cn+1 should, for example, the nozzle 124NX, at column Cn, pass over a top end portion of the sub-pixel formation region SP(B) belonging to row Rm in FIG. 9, or the angle θ be set to a small angle. However, even if the nozzle 124NX should pass over sub-pixel formation regions SP(B) in the same row Rm at both column Cn and column Cn+1, there will be at least one column beyond column Cn+1 (or before column Cn) at which the nozzle 124NX, moving with the angle θ kept the same, does not pass over

a sub-pixel formation region SP(B) belonging to row Rm. Particularly, in display panels, the length of an array of pixel formation regions P lining up in the row direction d1 is much greater than the size of a single pixel formation region P. Due to this, even if the angle θ is set to an extremely small angle, the nozzle 124N would apply the ink 16a across multiple rows as long as the scanning direction ds, defined by the angle θ , is inclined with respect to the row direction d1.

As such, in the panel 10, which is manufactured according to the above-described method, the risk is low of faulty pixels lining up in the row direction d1. Here, faulty pixels refer to pixels having high or low luminance compared to other pixels, pixels not emitting any light, or pixels emitting a color not matching the desired color, produced due to the difference in discharge amounts of the nozzles 124N. Accordingly, the manufacturing method pertaining to the present embodiment reduces the risk of occurrence of a linear unevenness in luminance, light-emission color, etc., along the row direction d1 (i.e., a pixel arrangement direction), caused by a difference in discharge amounts of nozzles.

5. Notes

(1) Beneficial Values of Angle θ

The manufacturing method of the panel 10 achieves the above-described effects when the angle θ is set to any angle more than 0° and less than 90°. Nevertheless, setting the angle θ to certain angles would produce additional effects.

For example, it is preferable that the angle θ be set to satisfy $Dp \times \tan \theta \neq Dp2$, for Dp denoting the pitch between pixel formation regions P lining up in the row direction d1 and Dp2 denoting the pitch between pixel formation regions lining up in the column direction d2. Setting the angle θ to satisfy $Dp \times \tan \theta \neq Dp2$ is preferable for the following reason. When angle θ is set to satisfy $Dp \times \tan \theta = Dp2$, the scanning with the nozzle array 124 results in application positions of the nozzles 124N differing by exactly Dp2 from column to column. This means that the combinations of nozzles 124N performing application to the pixel formation regions P remaining the same. Accordingly, pixel formation regions P that are similar to one another in terms of the amount of the ink 16a applied thereto lining up in the scanning direction ds, which leads to a linear unevenness in luminance, light-emission color, etc., occurring along the scanning direction ds.

Meanwhile, when the angle θ is set to satisfy $Dp \times \tan \theta \neq Dp2$, the combination of nozzles 124N performing application changes from one pixel formation region P to another. Thus, the risk is reduced of occurrence of a linear unevenness in luminance, light-emission color, etc., along the scanning direction ds.

Also, in the manufacturing method of the panel 10, it is preferable that the angle θ be set so as to satisfy Math. 1, below, where N is a positive integer.

$$\theta = \sin^{-1} \left(\frac{N \cdot Dn \cdot \sin \alpha}{Dp} \right) \quad [\text{Math. 1}]$$

FIG. 10A is a diagram illustrating pitch Dd1 between application positions of adjacent nozzles 124Na and 124Nb in a sub-pixel formation region SP, and FIG. 10B is a diagram illustrating an offset Dd2 in the column direction d2 between application positions A3 and A4 of one nozzle in adjacent pixel formation regions P.

According to FIG. 10A, with α denoting the angle between the extension direction dh and the scanning direc-

tion ds of the nozzle array **124**, $D1 \cdot \cos \theta = Dn \cdot \sin \alpha$ is satisfied, where Dn denotes the pitch between adjacent nozzles **124Na** and **124Nb**, and $Dd1$ denotes the pitch between application positions **A1** and **A2** of the ink **16a** within one sub-pixel formation region **SP**, respectively corresponding to the nozzles **124Na** and **124Nb**.

Also, as illustrated in FIG. **10B**, $Dd2 = Dp \cdot \tan \theta$ is satisfied, where $Dd2$ denotes an offset in the column direction **d2** between application position **A3** in one column receiving the ink **16a** from a nozzle **124N** (undepicted) and application position **A4** in an adjacent column receiving the ink **16a** from the same nozzle **124N**.

Here, when the angle θ satisfies Math. 1 given above, then $Dd2 = Dp \cdot (\sin \theta / \cos \theta) = (N \cdot Dn \cdot \sin \alpha) / \cos \theta = N \cdot Dd1$. This means that between pixel formation regions **P** adjacent in the row direction **d1**, the position in the column direction **d2** above which a same nozzle **124N** passes (application position **A**) differs by exactly N (positive integer) times the pitch $Dd1$ between application positions of the ink **16a**. Accordingly, nozzles **124N** pass above the same column-direction positions of all pixel formation regions **P** lining up along the row direction **d1**. That is, application positions **A** of the ink **16a** remain the same in all pixel formation regions **P** lining up in the row direction **d1**. Thus, the risk is low of positions in the column direction **d2**, numbers, etc., of application positions **A** differing among pixel formation regions **P** lining up in the row direction **d1**. Thus, the risk is reduced of occurrence of application unevenness along the row direction **d1**. Accordingly, setting the angle θ to satisfy Math. 1 reduces the risk of occurrence of a linear unevenness in luminance, light-emission color, etc., along the row direction **d1**.

(2) Value of N for Sub-Pixel Formation Regions **SP**

As described above, when the angle θ satisfies Math. 1, the application positions **A** of nozzles **124N** in one pixel formation region **P** differ in the column direction **d2** by $N \cdot Dd1$ from the application positions **A** of nozzles **124N** in a pixel formation region **P** adjacent in the row direction **d1**. In other words, N indicates the number of nozzles **124N** that are replaced with other nozzles **124N** between pixel formation regions **P** adjacent in the row direction **d1**. Accordingly, the larger the value of N , the smaller the risk of the influence of the difference among the nozzles **124N** appearing in the row direction **d1**. Thus, the larger the value set to N , the lower the risk of occurrence of a linear unevenness in luminance, light-emission color, etc.

Here, in the panel **10**, each pixel formation region **P** has sub-pixel formation regions **SP(R)**, **SP(G)**, and **SP(B)**, respectively corresponding to the colors red (R), green (G), and blue (B). Further, different inks **16a** are applied to sub-pixel formation regions of different colors, in order to form light-emitting layers having different light emission colors. In the following, the different inks applied to the sub-pixel formation regions **SP(R)**, **SP(G)**, and **SP(B)** are respectively referred to as a first ink **16a(R)**, a second ink **16a(G)**, and a third ink **16a(B)**. Further, when there is a need to refer to these ink collectively, the term inks **16a (R), (G), (B)** is used.

In the manufacturing method of the panel **10**, it is preferable that the application of the different inks **16a (R), (G), and (B)** be performed separately by performing scanning with the nozzle array **124** each time with respect to only the corresponding sub-pixel formation regions (i.e., the sub-pixel formation regions **SP(R)**, the sub-pixel formation regions **SP(G)**, or the sub-pixel formation regions **SP(B)**). Performing scanning separately in such a manner allows varying the value of N among the different inks **16a (R), (G),**

and (B). Note that in the following, the scanning direction ds in the application of the first ink **16a (R)** is termed a first scanning direction $ds1$, the scanning direction ds in the application of the second ink **16a (G)** is termed a second scanning direction $ds2$, and the scanning direction ds in the application of the third ink **16a (B)** is termed a third scanning direction $ds3$.

FIG. **11** shows graphs indicating the relationship between application amount and relative luminance for samples of inks **16a**. In FIG. **11**, relative values are plotted on the horizontal axis and the vertical axis. The vertical axis plots application amounts of the samples of the inks **16a** relative to a predetermined application amount indicated by using the value 1, and the horizontal axis indicates change from a predetermined luminance. These graphs each indicate the relationship for a specific sample of a corresponding one of the inks **16a (R), (G), (B)**. Note that using other samples of the inks **16a (R), (G), (B)** would result in the relationship differing from that illustrated in FIG. **11**, specifically in the graphs having different inclinations.

As indicated in FIG. **11**, the dependency of luminance with respect to application amount differs among the samples of the inks **16a (R), (G), (B)**. Specifically, while luminance is very dependent upon application amount for the sample of the second ink **16a (G)**, luminance is not so dependent upon application amount for the sample of the third ink **16a (B)**. This is believed to reflect the fact that typically, human visual sensitivity is more sensitive to change in the color green and less sensitive to change in the color blue.

The above shows that the influence of the difference among the nozzles **124N** with respect to luminance is relatively great in the application of the sample of the second ink **16a (G)**. Thus, it is preferable that the angle θ be set so that the value N defining the second scanning direction $ds2$ in the application of the sample of the second ink **16a (G)** is greater than or equal to the value N defining the first scanning direction $ds1$ and the value N defining the third scanning direction $ds3$. More generally, it is preferable that the angle θ be set to that the value N defining the scanning direction in the application of one of the inks **16a (R), (G), (B)** for which luminance is most dependent upon application amount is equal to or greater than the value N defining the scanning direction in the application of each of the other ones of the inks **16a (R), (G), (B)**.

FIG. **12** shows graphs indicating the relationship between application amount variance and ratio N/TN for samples of inks **16a**. In FIG. **12**, application amount variance is plotted along the horizontal axis. Application amount variance differs for different samples of the ink **16a**, and application amount variance for a given sample of the ink **16a** is a percentage calculated by dividing, by average application amount when causing nozzles **124N** to discharge the sample of the ink **16a** multiple times, a greater one of a difference between the average application amount and the maximum application amount and a difference between the average application amount and the minimum application amount. Further, TN denotes the number of nozzles **124N** applying ink with respect to each sub-pixel formation region **SP** (the term application nozzle count TN is also used in the following). Accordingly, the ratio N/TN plotted along the vertical axis in FIG. **12** indicates the ratio of the number of nozzles **124N** that are replaced with other nozzles **124N** between pixel formation regions **P** adjacent in the row direction **d1**, to the application nozzle count TN .

The graphs of FIG. **12** deductively indicate the results of an observation that the present inventor conducted. In the

observation, the present inventor applied samples of inks **16a** of different colors to the corresponding sub-pixel formation regions with different angles θ , and checked the occurrence of linear unevenness in luminance in the sub-pixel formation regions SP. Specifically, the graphs of FIG. **12** indicate, with respect to the application amount variance of different samples of the ink **16a**, N/TN values with which the occurrence of linear unevenness in luminance is sufficiently prevented. For example, the graphs in FIG. **12** show that for one sample of the ink **16a** (R) whose application amount variance when applied with respect to the sub-pixel formation regions SP(R) was found to be 9% through the observation, the occurrence of linear unevenness in luminance can be sufficiently prevented by setting the angle θ such that N/TN is no less than 0.22.

FIG. **12** also shows, using dashed lines, straight lines approximating the results of the observation. For samples of the ink **16a**, it is preferable that the angle θ be set so that the N/TN value is above the corresponding straight line. That is, when denoting application amount variation as X %, it is preferable to set the angle θ to satisfy Math. 5 below for the first scanning direction ds1 (i.e., in the application of samples of the first ink **16a** (R)), and to satisfy Math. 6 below for the second scanning direction ds2 (i.e., in the application of samples of the second ink **16a** (G)).

$$\frac{N}{TN} \geq 0.05X - 0.23 \quad [\text{Math. 5}]$$

$$\frac{N}{TN} \geq 0.08X - 0.30 \quad [\text{Math. 6}]$$

Here, since the dependency of luminance on application amount is relatively low for the third scanning direction ds3 (i.e., in the application of samples of the third ink **16a** (B)), the N/TN value (i.e., the angle θ) for the third scanning direction ds3 may be set to any value.

(3) Preferable Relationship Between Angle θ and Shape of Sub-Pixel Formation Region SP

In the panel **10**, the apertures **15a**, that is, the sub-pixel formation regions SP are formed to have elongated shapes and such that a long-side direction thereof is orthogonal to the row direction d1. Specifically, as illustrated in FIG. **2**, the sub-pixel formation regions SP are each formed to have a substantially elliptical shape having the column direction d2 as a major axis direction and having the row direction d1 as a minor axis direction.

Here, in the application of the ink **16a** with respect to the sub-pixel formation regions SP, the greater the application nozzle count TN, the relatively smaller the influence of difference in discharge amounts of the nozzles **124N**. In order to increase the application nozzle count TN, it is preferable that the scanning direction ds (i.e., first scanning direction ds1, the second scanning direction ds2, and the third scanning direction ds3) of the nozzle array **124** is set closer to the minor axis direction d1 of the sub-pixel formation regions SP than the major axis direction d2 of the sub-pixel formation regions SP. In other words, it is preferable to set the angle between the scanning direction ds of the nozzle array **124** and the minor axis direction d1 of the sub-pixel formation regions SP, that is, the angle θ , to be greater than 0° and no more than 45°.

(4) Preferable Range of N

In the application of the ink **16a** with respect to the sub-pixel formation regions SP, it is preferable to set the

angle θ to satisfy Math. 2 below, where Lsp denotes the length of the sub-pixel formation regions SP in the long-side direction thereof.

$$\theta \leq \tan^{-1} \left(\frac{Lsp}{Dp} \right) \quad [\text{Math. 2}]$$

FIG. **13** is a schematic plan view diagram illustrating scanning of the sub-pixel formation regions SP with the nozzle array **124** and with the angles θ and α . According to FIG. **13**, the application nozzle count TN is either $[(Lsp \cdot \cos \theta) / (Dn \cdot \sin \alpha)]$ or $[(Lsp \cdot \cos \theta) / (Dn \cdot \sin \alpha)] + 1$. Here, the symbols in square brackets are Gauss symbols, where $[A]$ represents a maximum integer not exceeding A. Accordingly, A is no less than $[A]$ and less than $[A] + 1$.

Meanwhile, as described above, N indicates the number of nozzles **124N** that are replaced with other nozzles **124N** between pixel formation regions P adjacent in the row direction d1. Here, when the angle θ satisfies the equation of Math. 2, N is expressible as: $N = Dd2 / Dd1 = (Dp \cdot \tan \theta) / ((Dn \cdot \sin \alpha) / \cos \theta) = (Lsp \cdot \cos \theta) / (Dn \cdot \sin \alpha)$. Thus, N is nearly equal to the application nozzle count TN.

This means that, when the angle θ satisfies the equation of Math. 2, the nozzles **124N** used for application are almost completely replaced between pixel formation regions P adjacent in the row direction d1, and thus the influence of the difference in discharge amount among the nozzles **124N** barely appears in the row direction d1. Meanwhile, setting angles greater than this to angle θ brings about substantially no change in terms of the effect of reducing the risk of occurrence of linear unevenness in luminance, light-emission color, etc. In fact, setting angles greater than this to angle θ brings about problems such as an increase in the number of nozzles **124N** required to perform application with respect to all of the sub-pixel formation region SP, and a risk arising of the influence of the difference in discharge amount among the nozzles **124N** appearing in the column direction d2. Thus, it is preferable that N is no greater than TN, and in other words, it is preferable that the angle θ is set to satisfy Math. 2.

(5) Preferable Range of Angle α

Angle α is the angle between the scanning direction ds and the extension direction dh of the nozzle array **124**, and is a parameter changing the application pitch Dd1. It is preferable that angles α and θ satisfy Math. 3 below.

$$\alpha \leq 90^\circ - \theta \quad [\text{Math. 3}]$$

When Math. 3 is satisfied, the application nozzle count TN satisfies the inequality of Math 7 below.

$$TN \geq \left\lceil \frac{Lsp \cdot \cos \theta}{Dn \cdot \sin \alpha} \right\rceil \geq \left\lceil \frac{Lsp \cdot \cos \theta}{Dn \cdot \sin(90^\circ - \theta)} \right\rceil = \left\lceil \frac{Lsp}{Dn} \right\rceil \quad [\text{Math. 7}]$$

Here, the right-hand side of Math. 7 is substantially equal to the application nozzle count when $\theta = 0^\circ$ and $\alpha = 90^\circ$, in other words, the application nozzle count in typical inkjet application. Thus, setting the angle α to satisfy Math. 3 ensures that the application nozzle count TN is at least equal to the application nozzle count in typical inkjet application, and thus, the risk can be reduced of the occurrence of a linear unevenness in luminance, light-emission color, etc., without bringing about an increase in variance among pixels in terms of luminance, light-emission color, etc.

(6) Scan Count Relative to Angle θ

In the application of the ink **16a** with respect to the sub-pixel formation regions SP, it is preferable the angle θ is set to satisfy Math. 4 below, where W denotes the length of the substrate **11** in the long-side direction, H denotes the length of the substrate **11** in the short-side direction, and L denotes the length of the nozzle array **124** in the extension direction dh.

$$\left\lceil \frac{H \cos \theta + W \sin \theta}{L \sin \alpha} \right\rceil = \left\lceil \frac{H}{L \sin \alpha} \right\rceil \quad [\text{Math. 4}]$$

FIG. **14** is a schematic plan view diagram describing the number of times the inkjet device **100** performs scanning (referred to as scan count in the following). FIG. **14** illustrates an example where the inkjet head **122** depicted at the right-hand side of the page moves in the scanning direction ds and applies the ink **16a** over the substrate **11**.

As illustrated in FIG. **14**, when performing scanning with the nozzle array **124** and with the angles θ and α , the minimum scan count required in order to apply the ink **16a** over the entire surface of the substrate **11** can be calculated by adding one to the left-hand side value of Math. 4. Meanwhile, when the angle θ is 0° , the minimum scan count can be calculated by adding one to the right-hand side value of Math. 4. This means that when Math. 4 is satisfied, the ink **16a** can be applied over the entire surface of the substrate **11** without increasing the scan count from that in typical inkjet application. Thus, an increase in manufacturing procedures can be prevented.

Note that in the description above, the difference between the size of the image display face of the substrate **11** and the size of the pixel arrangement region is not considered for being presumably small (that is, the vessel portion is not considered), and also, the difference between the length of the inkjet head **122** in the long-side direction thereof and the total length L of the nozzle array **124** is not considered for being presumably small.

(7) Other Matters

In mathematical formulae Math. 1 through Math. 7 given in the present disclosure, equalities therein need not be satisfied in a strict sense, and instead, the equalities may be considered to be established when there is a match in a practical level. For example, when comparing a right-hand side and a left-hand side of an equation, equality may be considered to be established between the left-hand side and the right-hand side when the leading two significant figures match.

In the present embodiment, the nozzles **124N** in the inkjet device **100** line up to form one straight line. However, the nozzles **124N** need not form a single straight line. FIG. **15** is a perspective view diagram indicating an inkjet device **200** pertaining to a modification. In the inkjet device **200**, a head unit **220** has a plurality of inkjet heads **222** attached thereto, and each inkjet head has a plurality of nozzles **124N** lining up in a straight line. That is, the nozzles **124N** may line up to form two or more linear arrays, provided that the linear arrays are parallel to one another.

In the present embodiment, the inkjet device **100** sets the angle θ between the row direction d1, which is one direction in which sub-pixel formation regions SP line up, and the scanning direction ds by rotating the substrate **11** over the base **111**. Alternatively, for example, the substrate **11** may be fixed with respect to the base **111**, and the scanning direction

ds may be set by configuring the guide shafts **113a** and **113b** to be freely rotatable within the plane parallel to the top surface of the base **111**.

In the present embodiment, the nozzles **124N** of the inkjet device **100** are moved in the scanning direction ds. Alternatively, the nozzles **124N** may be displaced relative to the scanning direction ds by moving the substrate **11** in a direction opposite the scanning direction ds.

In the present embodiment, the angle θ in the application of the ink **16a** is the angle between the scanning direction ds of the nozzle array **124** and the row direction d1, which is one direction in which pixel formation regions P line up. Alternatively, the angle θ may also be considered to be an angle between the scanning direction ds and the column direction d2, which is the other direction in which pixel formation regions P line up.

In the present embodiment, inkjet application is used for forming the light-emitting layers **16**. Inkjet application may also be used for forming functional layers other than the light-emitting layers **16** (e.g., the electron transport layer **17**). Application amount (layer thickness) in the forming of functional layers other than the light-emitting layer **16** may also affect pixel luminance. Thus, the risk of occurrence of linear unevenness in luminance, light-emission color, etc., in the row direction d1 may be reduced by additionally setting the angle between the row direction d1 and the scanning direction ds to be greater than 0° and less than 90° in the forming of functional layers other than the light-emitting layer **16**.

In the panel **10** pertaining to the present embodiment, the row direction (d1) and the column direction (d2), which are the directions in which pixel formation regions P line up, are parallel to the long-side direction and the short-side direction of the substrate **11**, respectively. Alternatively, for example, at least one of the row direction d1 and the column direction d2 may be neither parallel nor orthogonal to the long-side direction or the short-side direction of the substrate **11**. In addition, the row direction d1 and the column direction d2 need not be orthogonal to one another. Note that the risk of occurrence of linear unevenness in luminance, light-emission color, etc., in both the row direction and the column direction can be reduced by setting the scanning direction ds to be inclined (by angle θ) with respect to both the row direction d1 and the column direction d2. That is, there is no substantial distinction between the row direction d1 and the column direction d2. Thus, replacing these directions with one another (using the column direction d2 as the "row direction") does not bring about any problems.

In the panel **10**, each pixel formation region P includes sub-pixel formation regions SP corresponding to the three colors red, green, and blue. Alternatively, each pixel formation region P may include sub-pixel formation region(s) SP for only the color red or for the four colors red, green, blue, and yellow. Also, each sub-pixel formation regions SP need not include one sub-pixel formation region SP per color. That is, each sub-pixel formation regions SP may include two or more sub-pixel formation regions SP per color. Furthermore, sub-pixel formation regions SP in each pixel formation region P need not line up in the row direction d1, and instead, may line up in the column direction, or may be arranged positions resembling peaks of a triangle. Note that when making a modification such that each pixel formation region P includes only one sub-pixel formation region SP, all passages in the present embodiment where the term "sub-pixel formation region SP" is used can be correctly understood by replacing the term "sub-pixel formation region SP" with the term "pixel formation region P".

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In the panel **10**, the main body of the substrate **11** (portion excluding the TFT layer) has a rectangular shape. Alternatively, the main body of the substrate **11** may have a square shape, a polygonal shape other than a rectangular shape, a circular shape, or an elliptical shape.

In the panel **10**, the first electrodes **12** serve as anodes and the second electrode **18** serves as a cathode. Alternatively, an inverse structure may be adopted in which the first electrodes **12** serve as cathodes and the second electrode **18** serves as an anode.

In the panel **10**, the banks **15** may surround each of the sub-pixel formation regions SP (pixel bank scheme), or may for example surround each line of sub-pixel formation regions SP in the column direction **d2** (line bank scheme). When the aforementioned line bank scheme is used, barriers (pixel definition layers) preventing cross-talk between sub-pixel formation regions SP adjacent in the column direction **d2** are typically disposed. Accordingly, ink flow in the column direction **d2** is limited regardless of the bank scheme applied, since in the line banks scheme, the barriers limit ink flow in the column direction **d2**. Thus, the manufacturing method pertaining to the present embodiment, which reduces the risk of difference in discharge amount among the nozzles **124N** being reflected in the row direction **d1**, is useful also with the line bank scheme.

In the present embodiment, the panel **10** is a top-emission-type organic EL display panel using the active matrix scheme. Alternatively, for example, the panel **10** may be a bottom-emission-type organic EL display panel and/or use the passive matrix scheme. When making such modifications, the structure and the manufacturing method of the panel **10** are accordingly changed as necessary.

INDUSTRIAL APPLICABILITY

The organic EL display panel manufacturing method pertaining to the present invention is widely applicable as a manufacturing method of display panels usable in various electronic devices, such as televisions, personal computers, commercial displays, and portable terminals.

REFERENCE SIGNS LIST

- 10** Organic EL display panel
- 11** Substrate
- 12** First electrode
- 15** Bank
- 16** Light-emitting layer (functional layer)
- 16a** Ink
- 18** Second electrode
- 124N, 824N, 924N** Nozzle
- Dp, Dp2** Pixel pitch
- Dn** Nozzle pitch
- Lsp** Length
- N** Positive integer
- P** Pixel formation region
- SP** Sub-pixel formation region
- d1** Row direction
- d2** Column direction
- ds, dsx** Scanning direction
- α, θ Angle

The invention claimed is:

1. A method for manufacturing an organic EL display panel, the method comprising:
 - preparing a substrate;
 - forming a plurality of first electrodes over the substrate;

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defining, above the substrate, a plurality of pixel formation regions lining up in a row direction and a column direction to form a matrix, by forming banks over the substrate having the first electrodes formed thereon;

applying ink containing functional material to each of the pixel formation regions by causing a plurality of nozzles lining up in a straight line to discharge the ink to the pixel formation regions while displacing the nozzles relative to the substrate in a scanning direction along a main surface of the substrate;

drying the ink having been applied to form functional layers containing the functional material in the pixel formation regions; and

forming one or more layers, at least including a second electrode, at a position covering the pixel formation regions having the functional layers formed therein, wherein:

in the application of ink, an angle θ between the scanning direction and the row direction is set to more than 0° and less than 90° and each of the nozzles applies the ink across a plurality of rows of the pixel formation regions,

the pixel formation regions are defined to be located at a fixed pitch **Dp** in the row direction and at a fixed pitch **Dp2** in the column direction,

in the application of ink, the angle θ is set to satisfy:

$$Dp \times \tan \theta \neq Dp2, \quad [\text{Math. 1}]$$

in the application of ink, the angle θ is set to satisfy:

$$\theta = \sin^{-1} \left(\frac{N \cdot Dn \cdot \sin \alpha}{Dp} \right) \quad [\text{Math. 2}]$$

where **Dn** denotes a fixed pitch between the nozzles, α denotes an angle between the scanning direction and the straight line, and **N** is a positive integer,

the pixel formation regions are defined to each include sub-pixel formation regions corresponding to colors red, green, and blue,

ink application with the nozzles is performed separately, by using different inks, for sub-pixel formation regions corresponding to the color red, sub-pixel formation regions corresponding to the color green, and sub-pixel formation regions corresponding to the color blue,

the positive integer **N** for angle θ defining the scanning direction in application of one of the inks with which luminance is most dependent upon application amount is larger than the positive integer **N** for angle θ defining the scanning direction in application of each of the other ones of the inks, and

the applying ink step includes (1) obtaining angle θ for each ink of the respective different inks of the sub-pixel formation region, where each angle θ is set using Math. 1 and Math. 2, and (2) using the obtained angles θ to discharge the respective different inks for the sub-pixel formation regions.

2. The method according to claim 1, wherein the sub-pixel formation regions are each elongated in a direction orthogonal to the row direction, and in the application of any of the inks, the angle θ defining the scanning direction is set to more than 0° and less than 45° .

3. The method according to claim 2, wherein in the application of any of the inks, the angle θ defining the scanning direction is set to satisfy:

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$$\theta \leq \tan^{-1} \left(\frac{Lsp}{Dp} \right)$$

[Math. 3]

where Lsp denotes the length of the sub-pixel formation regions in the direction orthogonal to the row direction.

4. The method according to claim 3, wherein in the application of any of the inks, the angles A and a defining the scanning direction are set to satisfy:

$$\alpha \leq 90^\circ - \theta.$$

[Math. 4]

5. The method according to claim 4, wherein the main surface of the substrate has a rectangular shape, the pixel formation regions are defined so that the row direction matches a direction in which long sides of the substrate extend and the column direction matches a direction in which short sides of the substrate extend, and

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in the application of any of the inks, the angle θ defining the scanning direction is set to satisfy:

$$\left[\frac{H \cos \theta + W \sin \theta}{L \sin \alpha} \right] = \left[\frac{H}{L \sin \alpha} \right]$$

[Math. 5]

where W denotes a length of the long sides of the substrate, H denotes a length of the short sides of the substrate, and L denotes a length of the array of the nozzles.

6. The method according to claim 1, wherein the positive integer N for angle θ defining the scanning direction in application of a green ink with which luminance is most dependent upon application amount is larger than the positive integer N for angle θ defining the scanning direction in application of blue and red inks.

* * * * *

专利名称(译)	有机EL显示面板的制造方法		
公开(公告)号	US10541367	公开(公告)日	2020-01-21
申请号	US15/302900	申请日	2015-03-27
申请(专利权)人(译)	JOLED INC.		
当前申请(专利权)人(译)	JOLED INC.		
[标]发明人	TAKAHASHI YASUYUKI		
发明人	TAKAHASHI, YASUYUKI		
IPC分类号	H01L51/00 H05B33/10 B05D3/02 B05D1/26 B05D1/36 H01L51/56		
CPC分类号	H01L51/56 B05D1/36 H05B33/10 H01L51/0005 B05D1/26 B05D3/0254 B41J2/2135 B41J25/003		
代理机构(译)	MCDERMOTT WILL & EMERY LLP		
优先权	2014081099 2014-04-10 JP		
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摘要(译)

一种用于制造有机EL显示面板的方法，包括：在基板上形成第一电极；以及在基板上形成第一电极。通过在基板上形成堤，在基板上方限定在行方向和列方向上排列的像素形成区域；通过使多个喷嘴在一条直线上排成一行，以在相对于基板在扫描方向上相对于喷嘴移动的同时，将墨排出到像素形成区域，从而将墨施加到每个像素形成区域；干燥墨水以在像素形成区域中形成功能层；在覆盖像素形成区域的位置形成第二电极。在施加墨水时，将扫描方向与行方向之间的角度 θ 设置为大于 0° 且小于 90° ，并且每个喷嘴跨多行像素形成区域施加墨水。

